



MT7697 DATASHEET

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1 System Overview

1.1 General Description

MT7697 is a highly integrated single chip which features an application processor, a low power 1x1 11n single-band Wi-Fi subsystem, a Bluetooth subsystem, and a Power Management Unit. The application processor subsystem contains an ARM Cortex-M4 with floating point MCU. It also includes many peripherals, including UART, I2C, SPI, I2S, PWM, IrDA, and auxiliary ADC. It also includes embedded SRAM/ROM .

The Wi-Fi subsystem contains the 802.11b/g/n radio, baseband, and MAC that are designed to meet both the low power and high throughput application. It also contains a 32-bit RISC CPU that could fully offload the application processor.

The Bluetooth subsystem contains the Bluetooth radio, baseband, link controller. It also uses the same 32-bit RISC CPU for the Bluetooth protocols.

1.2 Features

1.2.1 Technology and package

- 8mm x 8mm 68-pin QFN package.

1.2.2 Power management and clock source

- Integrate high efficiency power management unit with single 3.3V power supply input
- 40/26/52MHz source crystal clock support with low power operation in idle mode

1.2.3 Platform

- ARM Cortex M4 MCU with FPU with up to 192MHz clock speed
- Embedded 352KB SRAM and 64KB boot ROM
- Supports external serial flash with Quad Peripheral Interface (QPI) mode
- Supports eXecute In Place (XIP) on flash
- 32KB cache in XIP mode
- Hardware crypto engines including AES, DES/3DES, SHA2 for network security
- 28 General Purpose IOs multiplexed with other interfaces
- Two UART interfaces with hardware flow control and one UART for debug, all multiplexed with GPIO
- One SPI master interface multiplexed with GPIO
- One SPI slave interface multiplexed with GPIO
- Two I2C master interface multiplexed with GPIO
- One I2S interface multiplexed with GPIO
- Four channel 12-bit ADC multiplexed with GPIO
- 28 PWM multiplexed with GPIO

- 25 channels DMA
- Low power RTC mode with 32KHz crystal support

1.2.4 WLAN

- Dedicated high-performance 32-bit RISC CPU N9 up to 160MHz clock speed
- IEEE 802.11 b/g/n compliant
- Supports 20MHz, 40MHz bandwidth in 2.4GHz band
- Single-band 1T1R mode with data rate up to 150Mbps
- Supports STBC, LDPC
- Greenfield, mixed mode, legacy modes support
- IEEE 802.11e support
- Security support for WFA WPA/WPA2 personal, WPS2.0
- Supports 802.11w protected managed frames
- QoS support of WFA WMM
- Integrated LNA, PA, and T/R switch
- Optional external LNA and PA support.
- RX diversity support with additional RX input

1.2.5 Bluetooth

- Bluetooth 4.2 Low Energy (LE)
- Integrated BALUN and PA
- Support SCO and eSCO link with re-transmission
- Channel assessment for AFH

1.2.6 Miscellaneous

- Integrates 4Kbit efuse to store device specific information and RF calibration data.
- Advanced Wi-Fi/Bluetooth coexistence scheme

1.3 Applications

MT7697 is designed for Internet-of-Things based on the MediaTek's low power technology, Wi-Fi and Bluetooth design.

1.4 Block Diagram

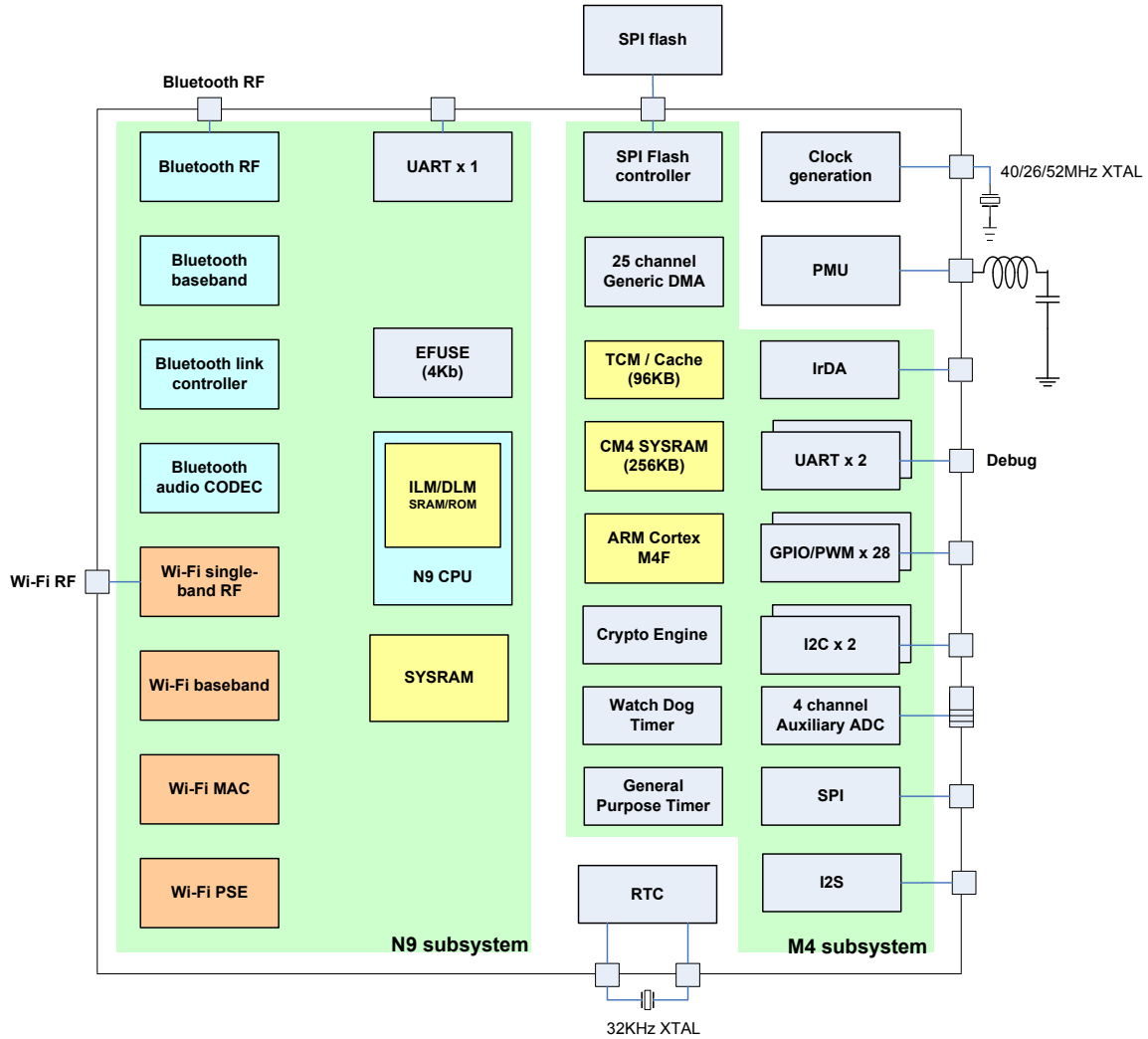


Figure 1-1. System-on-Chip Block Diagram

2 Functional Description

2.1 Overview

2.2 Power Management Unit

A single regulated 3.3V power supply is required for the MT7697. It could be from DC-DC converter to convert higher voltage supply to 3.3V or boost from a lower voltage supply to 3.3V.

The Power Management Unit (PMU) contains Under-Voltage Lockout (UVLO) circuit, several Low Drop-out Regulators (LDOs), a highly efficient buck converter, and a reference band-gap circuit. The circuits are optimized for low quiescent current, low drop-out voltage, efficient line/load regulation, high ripple rejection, and low output noise.

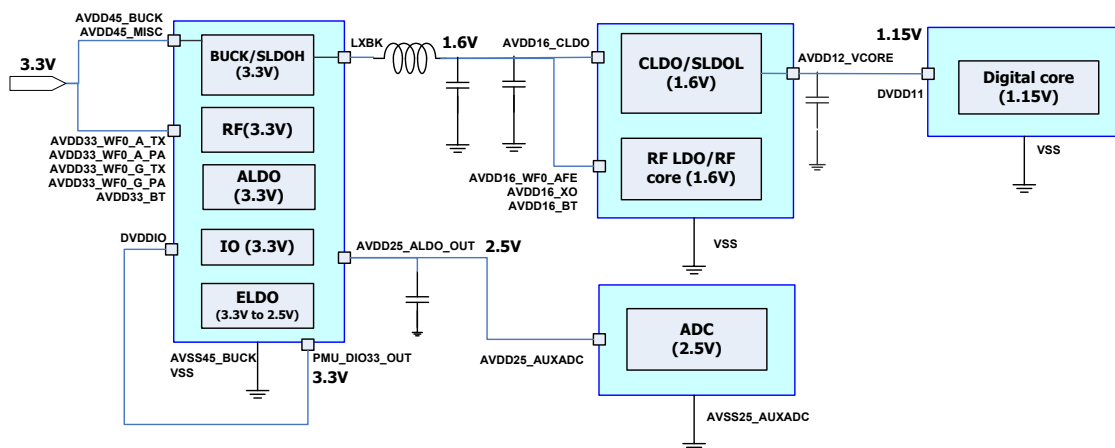


Figure 2-1. Chip Power Block Diagram

2.2.1 PMU Architecture

The PMU integrates 5 LDOs and one buck converter.

The four LDOs are CLDO, ALDO, high-voltage SLDO (SLDO-H) and low-voltage SLDO (SLDO-L). SLDO stands for sleep mode LDO, and CLDO stands for digital core LDO. The buck converter converts 1.6~1.8V output to other subsystems in MT7697. It can be operated in PFM mode or PWM mode. Through an external on-board LC filter (2.2uH inductor and 10uF cap), it outputs a low ripple 1.6~1.8V to Wi-Fi RF system, Bluetooth RF system, and CLDO. CLDO is under BUCK domain, and then it outputs 1.15V for whole chip digital logics used. ALDO is also from 3.3V chip supply input and generates 2.5V for the auxiliary ADC. The two SLDOs have 1.8V and 0.85V output voltage respectively. They are used to keep BUCK and CLDO output voltage while MT7697 is in sleep mode to reduce current consumption.

Once MT7697 goes into deep sleep mode, BUCK, ALDO, and CLDO can be shut down. BUCK output voltage will be kept by SLDO-H, and CLDO output will be kept by SLDO-L.

PMU also integrated the ELDO (Efuse LDO). It provides 2.5V output voltage to the internal Efuse macro in programming mode.

2.2.2 Chip Power Plan

The 3.3V power source is directly supplied to the switching regulator, digital I/Os, and RF-related circuit. It is converted to 2.5V by the LDO for ADC analog circuit. It is converted to 1.6V by the buck converter for low voltage circuits. The built-in digital LDOs and RF LDOs converts 1.6V to 1.15V for digital, RF, and BBPLL core circuits.

2.2.3 Digital Power Domain and Power States

The digital circuit is separated into five power domains. They are TOP_AON, TOP_OFF(N9), WF_OFF, BT_OFF, and CM4_SYS. Except TOP_AON, each power domain can be turned on and off individually.

Table 2-1. MTCMOS Power Domain

Domain	Description	Circuit Included	OFF Condition
TOP_AON	Always-on power domain, which keeps the minimum circuit powered to wake up from the sleep mode upon receiving a wake-up event.	It includes: Chip level configuration register. Sleep mode controller; External interrupt controller; Part of the Wi-Fi MAC that handles the beacon filtering. Sustain and backup memory that stores the RAM code and the register values that need to be kept during sleep mode.	N/A
TOP_OFF(N9)	The power domain can be power gated in Wi-Fi power save mode and Bluetooth power save mode.	The whole N9 subsystem, N9 peripherals, and part of the Wi-Fi MAC circuit are included.	N9 is in sleep mode and no DMA functions are enabled.

Domain	Description	Circuit Included	OFF Condition
WF_OFF	The power domain can be power gated when Wi-Fi is not used and in Wi-Fi power save mode.	The whole Wi-Fi baseband and part of the MAC subsystem are included.	Wi-Fi is disabled. N9 is in standby mode or in sleep mode.
BT_OFF	The power domain can be power gated when Bluetooth is not used and in Bluetooth power save mode.	The whole Bluetooth subsystem is included.	Bluetooth is disabled. N9 is in standby mode or in sleep mode.
CM4_OFF	The power domain is not powered gated when Cortex M4 is used.	The whole Cortex M4 subsystem and Cortex M4 peripherals are included.	N/A

The MT7697 power state diagram is illustrated below. There are two sleep mode controllers, controlled by N9 and CM4, respectively.

The N9 power state and CM4 power state operates independently. When both enter the sleep mode, the XTAL and PMU can be changed to the low power mode to further lower the current consumption.

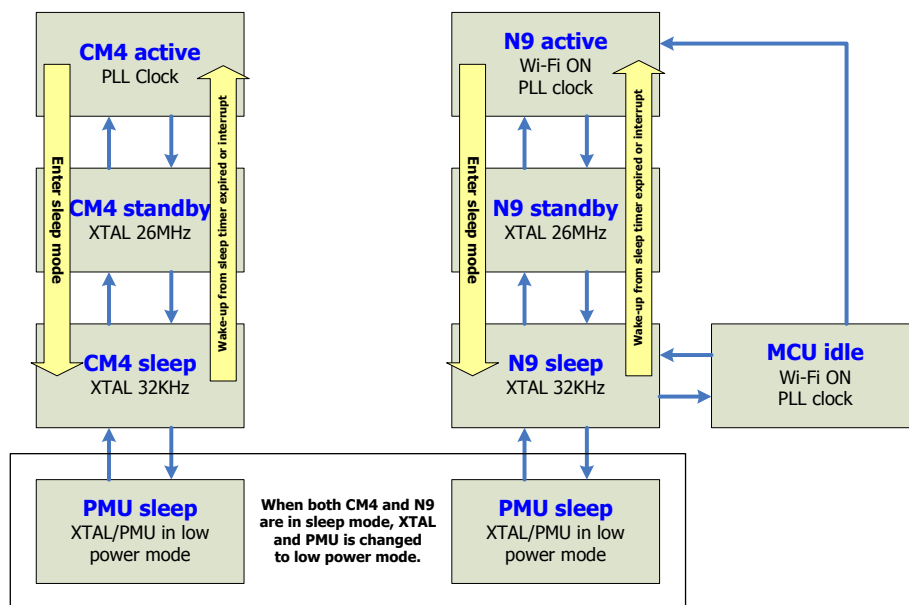


Figure 2-2. MT7697 Power State

Table 2-2. Power States for CM4 Subsystem

MCU mode	Description	Wake-up time	Power
CM4 active	MCU executing code at PLL clock	n/a	
CM4 standby	MCU subsystem clocks are gated off and the state of the entire subsystem is retained. PLL is off.	TBD	
CM4 sleep	MCU subsystem clocks are gated off and the state of the entire subsystem is retained. Only 32KHz clock from XTAL is active. MCU is configured to wake up on the expiry of the internal timer and external wake-up events.	TBD	1mA
PMU sleep	CM4_OFF is power gated. XTAL and PMU operate in low power mode. MCU is configured to wake up on the expiry of the internal timer and external wake-up events.	TBD	0.3mA

Table 2-3. Power States for N9 Subsystem

MCU mode	Description	Wake-up time	Power
N9 active	MCU executing code at PLL clock.	n/a	
MCU idle	MCU clock is gated off, while MCU subsystem clocks are on to maintain the operation of Wi-Fi function, like listening to beacon. PLL is on.	TBD	
N9 standby	MCU subsystem clocks are gated off and the state of the entire subsystem is retained. PLL is off.	TBD	
N9 sleep	MCU subsystem clocks are gated off and the state of the entire subsystem is retained. Only 32KHz clock from XTAL is active. MCU is configured to wake up on the expiry of the internal timer, external wake-up events, or the wake-up events from Wi-Fi radio or Bluetooth radio.	TBD	1mA
PMU sleep	TOP_OFF (N9) and WF_OFF are power gated. XTAL and PMU operate in low power mode. The state information is retained in back-up buffer (sleep-mode memory) and can be restored when wake-up. MCU is configured to wake up on the expiry of the	TBD	0.3mA

MCU mode	Description	Wake-up time	Power
	internal timer, external wake-up events, or the wake-up events from Wi-Fi radio or Bluetooth ratio.		

The typical scenarios which N9 operates in and the power state transition are summarized in the following table.

Table 2-4. Power State Transition Scenarios for N9

Scenario	Description	State transition
1	All functions are idle and the N9 firmware triggers to enter the sleep mode.	Active → Standby → Sleep
2	Wi-Fi DTIM timer is expired and the hardware wakes up to listen to beacon and then goes to sleep again when It is not necessary to wake up N9 to process the data.	Sleep → MCU idle (Wi-Fi ON) → sleep
3	Wi-Fi DTIM timer is expired and the hardware wakes up to listen to beacon and then wake up N9 to process the data.	Sleep → MCU idle (Wi-Fi ON) → Active

The typical scenarios which CM4 operates in and the power state transition are summarized in the following table.

Table 2-5. Power State Transition Scenarios for CM4

Scenario	Description	State transition
1	All functions are idle and the CM4 firmware triggers to enter the sleep mode.	Active → Standby → Sleep
2	The wake-up event (wake-up event from N9 or other sources) triggers CM4 to wake up.	Sleep → Standby → Active

2.3 Clock and Reset Generation

2.3.1 Clock

MT7697 connects to the XTAL or external clock source as the single clock source of the whole system. The XTAL oscillator can support the XTAL frequencies from among 40, 26, and 52MHz.

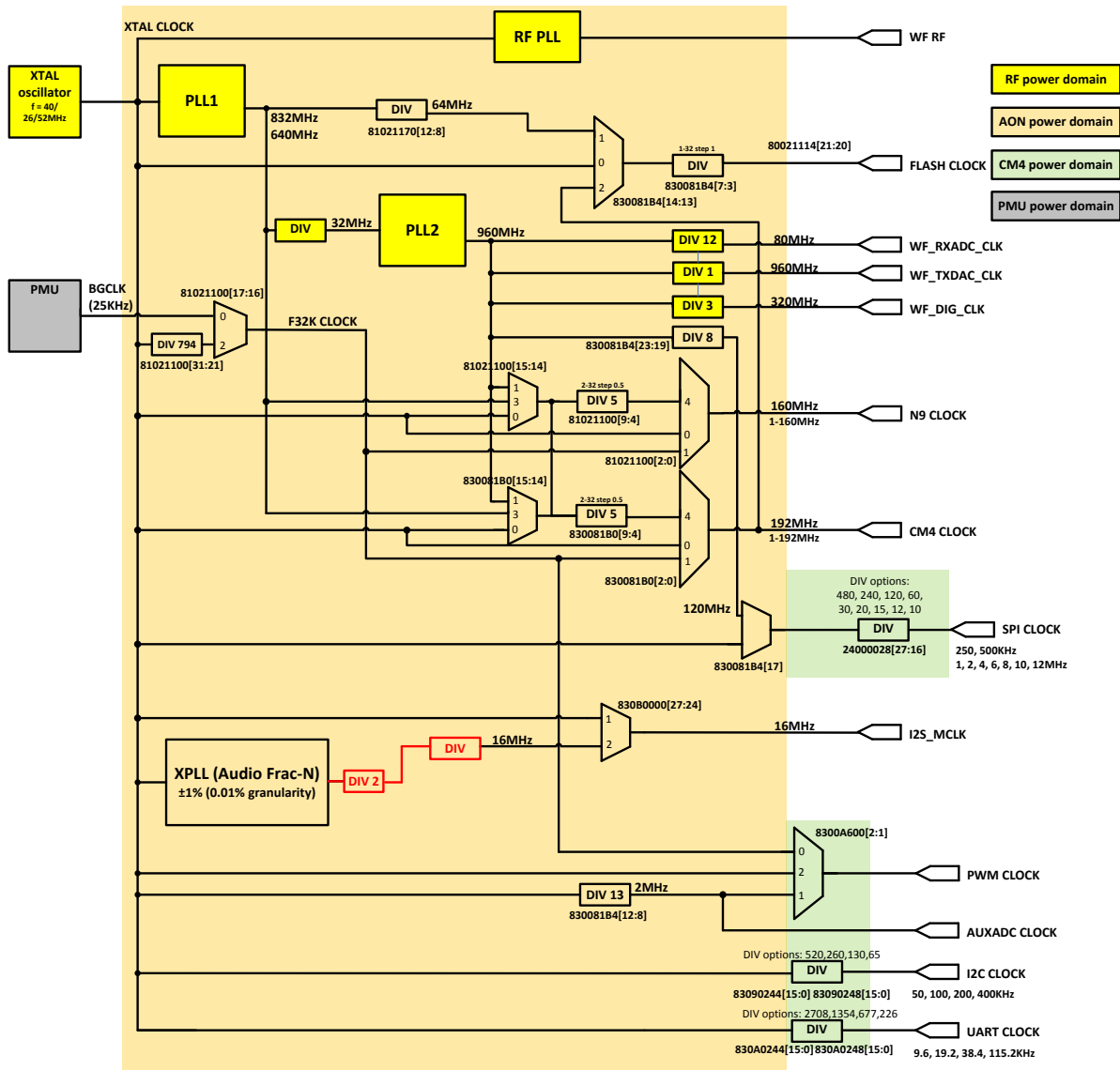


Figure 2-3. Clock Generation Block Diagram

- PLL1 is used to generate the clock sources for Bluetooth and PLL2.
- PLL2 is used to generate the clock sources for Wi-Fi, N9 core, Cortex M4 core, and bus fabric.
- XPLL is used to generate the clock sources for I2S (for external audio CODEC).

The options of clock rate for MCU are listed below.

Table 2-6. Cortex M4 Clock Rate

Reference Clock (MHz)	MCU Clock (MHz, XTAL mode)	MCU Clock (MHz, PLL mode)
40	40	30, 32, 40, 48, 60, 80, 96, 120, 160, 192.
26	26	
52	52	

Table 2-7. N9 Clock Rate

Reference Clock (MHz)	MCU Clock (MHz, XTAL mode)	MCU Clock (MHz, PLL mode)
40	40	30, 32, 40, 48, 60, 80, 96, 120, 160, 192.
26	26	
52	52	

Table 2-8. Peripheral Clock Rate

	Peripheral Clock Rate	Support SPEC
PWM	XTAL clock with DIV13 (Default)	200Hz at minimum.
	XTAL clock	
	F32K clock	
UART	XTAL clock with DIV	9.6, 19.2, 38.4, 115.2K
I2C	XTAL clock with DIV	50, 100, 200, 400KHz
SPI	XTAL clock with DIV (Default)	4, 6, 8, 10, 12MHz
Flash	XTAL clock with DIV (Default)	64MHz.
	BT_DIG_CLK (64MHz) with DIV	
	CM4 clock with DIV	

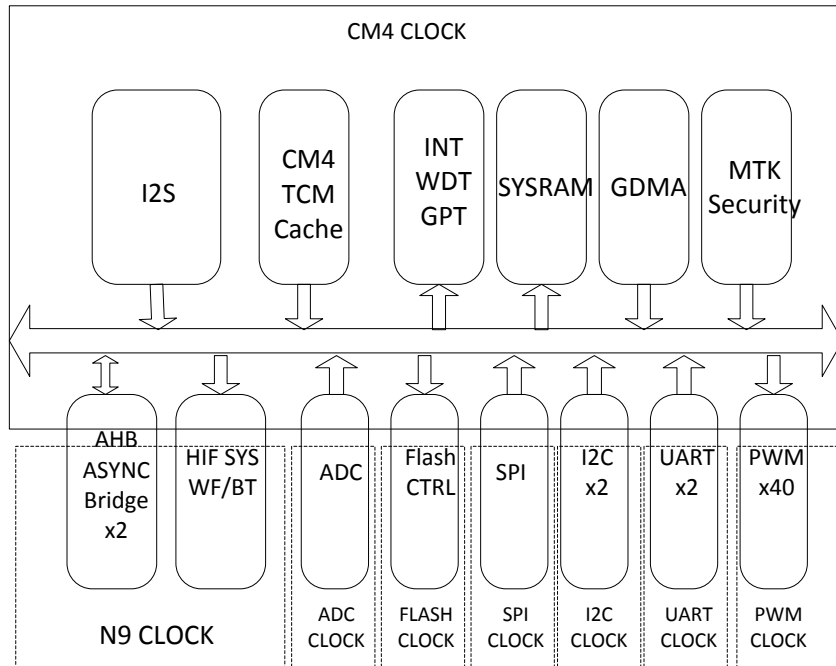


Figure 2-4. Clock Domains in N9 and CM4 Peripherals

2.3.2 Reset

MT7697 has three global resets: XRESETN, CM4_RESETN, and N9_RESETN. The figure below shows the module that the reset signals are applied to.

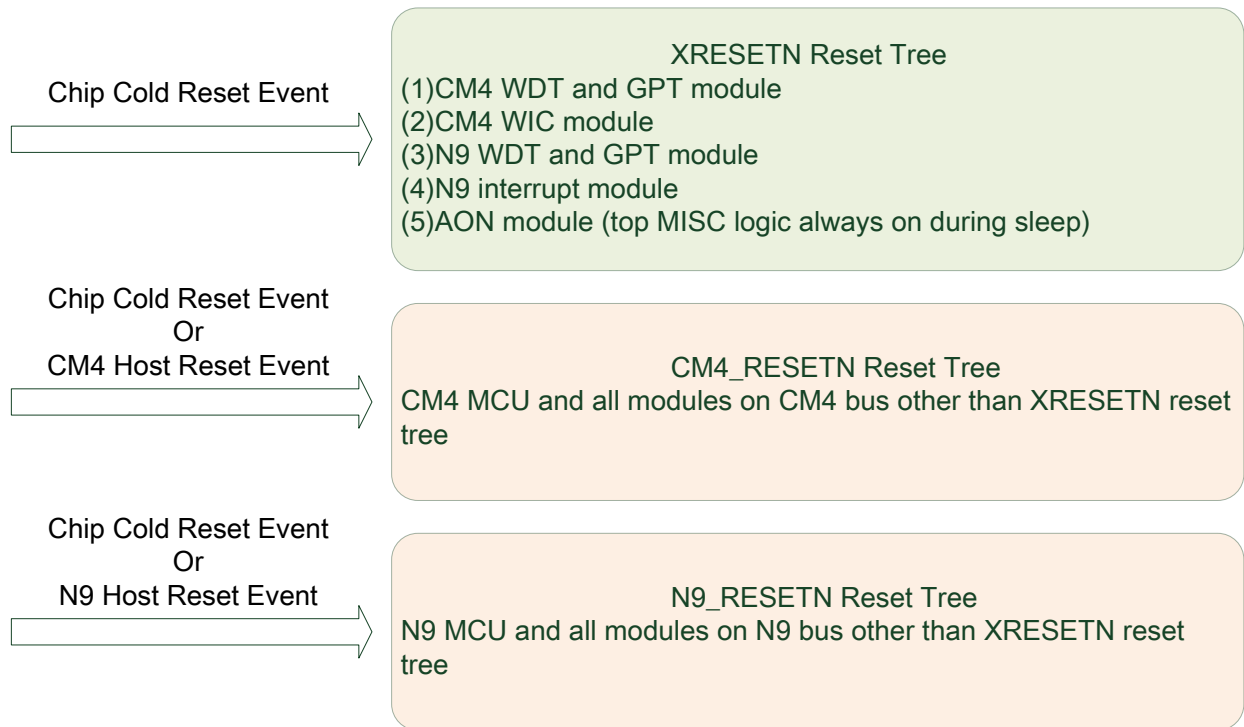


Figure 2-5. Reset Structure

2.4 Application Processor Subsystem

The MCU subsystem consists of a 32-bit MCU, the AHB/APB bus matrix, internal RAM/ROM with ROM patch function, the flash controller, and the system peripherals including Direct Memory Access (DMA) engine and the General Purpose Timer (GPT).

2.4.1 CPU

MT7697 features an ARM Cortex-M4 processor, which is the most energy efficient ARM processor available. It supports the clock rates from 1MHz up to 192MHz.

The MCU executes the Thumb-2 instruction set for optimal performance and code size, including hardware division, single cycle multiplication, and bit-field manipulation.

MT7697 includes the memory protection unit (MPU) in Cortex-M4 MCU that provides memory protection features. It can be used to detect unexpected memory access.

MT7697 also includes floating point unit (FPU) in Cortex-M4 process to support DSP related function.

2.4.2 Cache and Tightly Coupled Memory

MT7697 has a cache for Cortex-M4 to improve the efficiency of the code and data fetch from the external flash. The only cacheable memory region is the external flash.

MT7697 also has a Tightly-Coupled-Memory (TCM), a zero-wait-state memory which is dedicated for Cortex-M4 and can be accessed by Cortex-M4 exclusively. It is a memory space for the critical code such as interrupt service routines which needs to be executed with minimum latency. The DMA engines on AHB bus can't access TCM.

The total size of memory of the cache and the TCM is 96KB. Four software-configurable options differ in the size of cache, the size of TCM, and the cache associativity. The user can select the option which maximizes the performance.

The cache system has the following features:

- Configurable 1/2/4-way set associative (8KB/16KB/32KB)
- Each way has 256 cache lines with 8-word link size
- 20-bit tag memory: 19-bit high address and 1-bit valid bit
- 2-bit dirty memory: each dirty bit identifies the dirtiness of half cache line

The size of SRAM is 96KB. It can be configured to the following configuration

- 96KB TCM, no cache
- 88KB TCM, 8KB cache (1 way, direct mapped)
- 80KB TCM, 16KB cache (2 way set-associative)
- 64KB TCM, 32KB cache (4 way set-associative)

The configuration setting and the memory configuration are shown in the following table.

Table 2-9. TCM and Cache Configuration

0x0153_0000[9:8]	Functional Description	Start Address	End Address
00b	96KB TCM, no cache	0x0010_0000	0x0011_7FFF
01b	88KB TCM, 8KB cache, direct mapped	0x0010_0000	0x0011_5FFF
10b	80KB TCM, 16KB cache, 2-way set-associative	0x0010_0000	0x0011_3FFF
11b	64KB TCM, 32KB cache, 4-way set associative	0x0010_0000	0x0010_FFFF

The cache controller provides the user ways to perform cache operations including invalidate single/all cache lines as well as flush one/all cache lines.

To facilitate tuning the system performance, the cache controller can record the statistics of the cache hit count and the number of cacheable memory access. Cache hit rate can be obtained by dividing the cache hit count by the number of memory access.

2.4.3 Bus Fabric

MT7697 implements AHB/APB bus fabric to connect the MCU, memory, IO peripherals, and the radio subsystem.

- ILM/DLM: Instruction Local Memory / Data Local Memory, the zero-wait-state local memory for Radio MCU.
- Wi-Fi HIF: The data interface to Wi-Fi Packet switch engine.
- BT FIFO I/F: The control/data interface to Bluetooth subsystem.

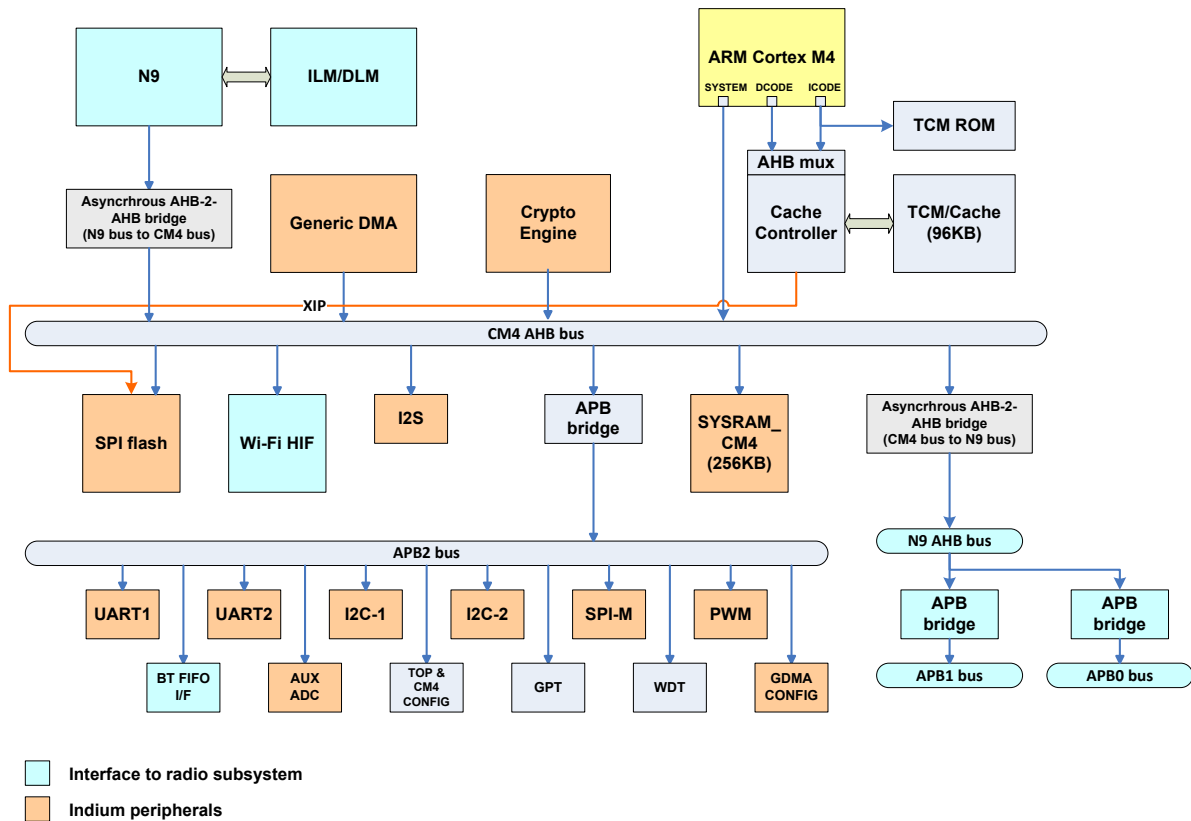


Figure 2-6. CM4 Subsystem – Bus Fabric

The AHB bus arbitration adopts round-robin scheme.

The N9 subsystem and Cortex M4 subsystem are in different clock domains, so the asynchronous bridges are inserted in the bus fabric. N9 has the ability to (but would be rarely used) all the M4 peripherals.

2.4.4 Serial Flash Controller

MT7697 features a serial flash controller that can support the serial flash with the read mode of (JEDEC) standard SPI mode, SPI-Quad mode, QPI (Quad Peripheral Interface) mode, Dual IO mode, and Dual-Output mode.

The frequency of the serial clock rate is up to 64MHz. That provides 256Mbps equivalent throughput on flash when SPI-quad mode or QPI mode is used.

Table 2-10. Flash Controller Support Read Mode

Read Mode	Description
SPI	1xIO for receiving command and address, 1xIO for output data
SPI-Quad	1xIO for receiving command, 4xIO for address, 4xIO for output data
QPI	4xIO for receiving command/address and output data
Dual-IO	1xIO for command, 2xIO for address and output data
Dual-Output	1xIO for receiving command, 2xIO for address and output data

The Serial Flash Controller Supports Two Operation Modes:

- Direct read mode, which supports a high-throughput direct-access through AHB bus
- Macro access mode, which supports flash access with arbitrary command and is through APB bus.

2.4.5 DMA

Direct memory access (DMA) is used to transfer data between memory ↔ memory as well as memory ↔ peripherals without MCU intervention.

2.4.5.1 DMA Functional Description

There are three types of DMA channels supported in MT7697.

- Full-size DMA: Both the source address and the destination address are programmable. It is normally used for memory copy.
- Half-size DMA: Either the source address or the destination address is programmable. It is normally used for data movement between memory and peripherals.
- Virtual FIFO DMA (VFF DMA): It is a half-size DMA with an additional FIFO control engine. It is used to provide the buffering capacity for peripherals including UART.

2.4.5.1.1 Virtual FIFO

Virtual FIFO DMA is designed to offload the control of the serial interface. The difference between the virtual FIFO DMA and the full-size/half-size DMA is that the virtual DMA contains an additional FIFO controller.

The figure below illustrates the operations of virtual FIFO DMA used for UART RX.

- READ: DMA controller reads data from UART and increments the WRITE pointer of the FIFO controller.
- WRITE; DMA controller writes data that was area from UART to SRAM in the area defined before enabling the virtual FIFO.
- READ: MCU reads data when FIFO is not empty and the amount of data is over a pre-defined threshold. The read transaction will be finished only when DMA controller reads back the data from SRAM.
- READ: DMA controller reads data from SRAM and increments the READ pointer of the FIFO controller.

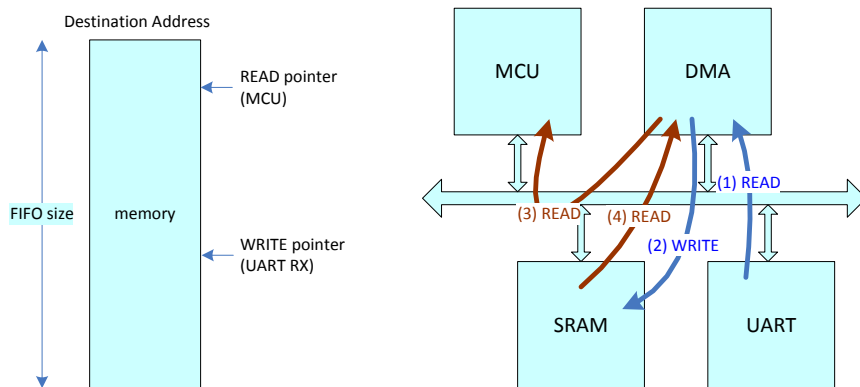


Figure 2-7. Virtual FIFO Concept

2.4.5.2 DMA Channels and Priority Control

There are two full-size DMA channels, 10 half- size DMA channels, and 13 virtual FIFO DMA channels in MT7697.

Table 2-11. DMA Use for Hardware Functions

Hardware Function	DMA Type
Radio (Bluetooth)	Virtual FIFO DMA x 2

Hardware Function	DMA Type
Radio (Wi-Fi)	Half size DMA x 1
UART (x2)	Virtual FIFO DMA x 4
I2S	Virtual FIFO DMA x 2
ADC	Virtual FIFO DMA x 1
I2C (x2)	Half size DMA x 4
SPI-M	Half size DMA x 2
Secure boot	Full size DMA x 1
Reserved	Full size DMA x 1, half size DMA x 3 and virtual FIFO DMA x 4.

The DMA provides two levels of scheduling scheme among all channels.

The 1st level scheduling follows the strict-priority scheme. All channels can be grouped into four priority groups. Group one gets the highest priority, then group two, and so on.

The 2nd level scheduling follows the round-robin scheme. Every channel in the same priority group has equal opportunity to use the bandwidth and was served sequentially.

The arbitration is done per AHB transaction. When one AHB transaction is finished, the scheduler will follow the above mechanism to select the next DMA channel to serve.

2.4.6 General Purpose Timer

MT7697 includes the General Purpose Timer (GPT).

Five independent timers are included. Timer 0, 1, and 3 are interrupt-based timers, while timer 2 and timer 4 are free-run timers.

Two modes are defined in interrupt-based timers:

- One-shot mode—the timer stops when the timer counts down to 0.
- Auto-repeat mode—the timer re-starts when the timer counts down to 0.

Table 2-12. General Purpose Timer Types

	Mode	Clock speed	Interrupt Source
GPT0	Interrupt-based	1KHz or 32KHz	GPT
GPT1	Interrupt-based	1KHz or 32KHz	
GPT2	Free-run	1KHz or 32KHz	n/a
GPT3	Interrupt based	26MHz (oscillator clock)	GPT3
GPT4	Free-run	Bus clock or bus clock / 2	n/a

2.4.7 Watchdog Timer

MT7697 features the watchdog timer for CM4, which is used to recover the system to the initial status when the system hangs due to some malfunction.

WDT provides two ways to generate the WDT event:

- Triggered by the time-out event (by configuring WDT_MODE:0x83080030 and WDT_LENGTH:0x83080034). The WDT has an 11-bit counter and it uses the 32 KHz clock. The software regularly restarts the timer to prevent it from expiring. If it fails to restart the WDT, the timer would expire and generate a WDT event.
- Triggered by software programming (WDT_SWRST:0x83080044).

WDT provides the following options when a WDT event is generated:

- 0x83080030[3]=0: Reset mode
 - 0x8300917C[16] = 1: WDT whole chip mode. Reset the whole chip including CM4 and N9 subsystems.
 - 0x8300917C[16] = 0: WDT MCU mode. Reset CM4 subsystem only.
- 0x83080030[3]=1: Interrupt mode
 - Issue an interrupt to CM4 instead of resetting whole chip or CM4 subsystem.

The WDT module can only be reset by the external reset (SYS_RST_N) and the PMU reset. Some WDT control registers feature a key protection mechanism such that an unintentional access would be prevented.

WDT also provides the capability for CM4 software to interrupt N9 or reset N9 (by configuring WDT_DUAL_CORE:0x83080080).

2.4.8 Efuse

MT7697 uses embedded Efuse to store device specific configuration information such as MAC addresses, and power control settings.

The major fields defined in the Efuse:

- Wi-Fi MAC addresses
- Wi-Fi country code
- Wi-Fi TSSI parameters, TX power level
- Wi-Fi NIC configuration: RF front-end configuration, LED mode, baseband configuration
- Bluetooth MAC address
- Bluetooth TX power level.

2.4.9 Interrupt Controller

MT7697 integrates the Nested Vectored Interrupt Controller (NVIC) for Cortex M4. The NVIC supports

- Level and pulse detection of interrupt signals
- Configurable priority
- Wake-up interrupt controller (WIC) providing ultra-low power sleep mode support

2.4.9.1 Interrupt Sources

The table below listed the NVIC and WIC interrupt sources. In total, there are 49 NVICs, while 23 of them are external interrupts multiplexed with GPIO functions.

The power domain/subsystem lists the power domain and the subsystem from which the interrupt is generated.

Table 2-13. CM4 NVIC Interrupt Source

NVIC No.	Interrupt source	Power domain / subsystem	External interrupt	Wake-up capability (1)	De-bounce	Description
INT0	UART1	CM4_OFF/MCUSYS_CM4				UART 1
INT1	DMA_CM4	CM4_OFF/MCUSYS_CM4				Generic DMA in CM4 subsystem
INT2	HIF_CM4	TOP_AON/HIFSYS		V		Wi-Fi host interface for CM4
INT3	I2C1	CM4_OFF/MCUSYS_CM4				I2C 1
INT4	I2C2	CM4_OFF/MCUSYS_CM4				I2C 2
INT5	UART2	CM4_OFF/MCUSYS_CM4				UART 2
INT6	CRYPTO	CM4_OFF/MCUSYS_CM4				Crypto engine
INT7	SF	CM4_OFF/MCUSYS_CM4				Serial flash controller, for debug
INT8	BTIF_N9_WAKE	TOP_OFF(N9)/MCUSYS_N9		V		Bluetooth interface in N9 subsystem to wake up CM4
INT9	BTIF	CM4_OFF/MCUSYS_CM4				Bluetooth interface in CM4

NVIC No.	Interrupt source	Power domain / subsystem	External interrupt	Wake-up capability (1)	De-bounce	Description
						subsystem
INT10	WDT_CM4	TOP_AON/MCUSYS_CM4		V		Watchdog timer in CM4 subsystem
INT11	N9_TO_CM4_SW1	TOP_AON/MCUSYS_N9		V		N9 software interrupt to CM4
INT12	SPI_S	CM4_OFF/MCUSYS_CM4				SPI slave
INT13	WDT_N9	TOP_AON/MCUSYS_N9		V		Watchdog timer in N9 subsystem
INT14	ADC	CM4_OFF/MCUSYS_CM4				Auxiliary ADC FIFO
INT15	IRTX	CM4_OFF/MCUSYS_CM4				IrDA TX
INT16	IRRX	CM4_OFF/MCUSYS_CM4				IrDA RX
INT17	(Reserved)					
INT18	(Reserved)					
INT19	RTC_TIMER	RTC		V		RTC timer interrupt
INT20	GPT3	CM4_OFF/MCUSYS_CM4		V		GPT3 time-out
INT21	RTC_ALARM	RTC		V		RTC alarm interrupt
INT22	(Reserved)					
INT23	N9_TO_CM4_SW2	TOP_AON/MCUSYS_N9		V		N9 software interrupt to CM4
INT24	GPT	TOP_CON/MCUSYS_CM4		V		GPT0 or GPT1 time-out
INT25	ADC_COMP	TOP_AON		V		ADC comparison mode
INT26	(Reserved)					
INT27	SPI	CM4_OFF/MCUSYS_CM4				SPI transaction
INT28	(Reserved)					
INT29	(Reserved)					
INT30	(Reserved)					
INT31	WIC	TOP_AON/MCUSYS_CM4		V ⁽²⁾		WIC WAKEUP interrupt CM4
INT32	SWD_CLK	TOP_AON	WIC[0]	V	Available	GPIO[2]
INT33	I2C1_DATA	TOP_AON	WIC[1]	V	Available	GPIO[25]
INT34	I2C0_CLK	TOP_AON	WIC[2]	V	Available	GPIO[27]
INT35	I2S_MCLK_S PI_MOSI	TOP_AON	WIC[3]	V	Available	GPIO[29]
INT36	I2S_BCLK_S PI_CS	TOP_AON	WIC[4]	V	Available	GPIO[32]
INT37	ANT_SEL0	TOP_AON	WIC[5]	V	Available	GPIO[33]
INT38	ANT_SEL1	TOP_AON	WIC[6]	V	Available	GPIO[34]
INT39	GPIO17	TOP_AON	WIC[7]	V	Available	GPIO[36]
INT40	ADC0	TOP_AON	WIC[8]	V	Available	GPIO[57]
INT41	ADC1	TOP_AON	WIC[9]	V	Available	GPIO[58]
INT42	ADC2	TOP_AON	WIC[10]	V	Available	GPIO[59]

NVIC No.	Interrupt source	Power domain / subsystem	External interrupt	Wake-up capability (1)	De-bounce	Description
INT43	ADC3	TOP_AON	WIC[11]	V	Available	GPIO[60]
INT56	PWM0	TOP_AON	EINT[0]	V	Available	GPIO[0]
INT57	PWM1	TOP_AON	EINT[1]	V	Available	GPIO[1]
INT58	SWD_DIO	TOP_AON	EINT[2]	V	Available	GPIO[3]
INT59	GPIO0	TOP_AON	EINT[3]	V	Available	GPIO[4]
INT60	GPIO1	TOP_AON	EINT[4]	V	Available	GPIO[5]
INT61	GPIO2	TOP_AON	EINT[5]	V	Available	GPIO[6]
INT62	GPIO3	TOP_AON	EINT[6]	V	Available	GPIO[7]
INT75	GPIO16	TOP_AON	EINT[19]	V	Available	GPIO[35]
INT76	GPIO18	TOP_AON	EINT[20]	V	Available	GPIO[37]
INT77	GPIO19	TOP_AON	EINT[21]	V	Available	GPIO[38]
INT78	GPIO20	TOP_AON	EINT[22]	V	Available	GPIO[39]

Note 1; Capable to wake up CM4 when CM4 is in sleep mode.

Note 2: This interrupt is associated with other wake-up interrupts for CM4 to differentiate wake-up interrupts from non wake-up interrupts.

2.4.9.2 External Interrupt

MT7697 has the optionally enabled hardware de-bouncing circuit for each interrupt source.

Table 2-14. CM4 External Interrupt De-Bounce Period

3-bit prescaler	Reference clock rate for de-bounce counter (KHz)	Minimum de-bounce period (ms)	Maximum de-bounce period (ms)
000	8	0.13	2
001	4	0.25	4
010	2	0.5	8
011	1	1	16
100	0.5	2	32
101	0.25	4	64
110	0.125	8	128

3-bit prescaler	Reference clock rate for de-bounce counter (KHz)	Minimum de-bounce period (ms)	Maximum de-bounce period (ms)
111	0.0625	16	256

2.4.10 Power-on Sequence

The power-on control sequence diagram shows how the code reset (PMU_RESET_N) is generated on chip.

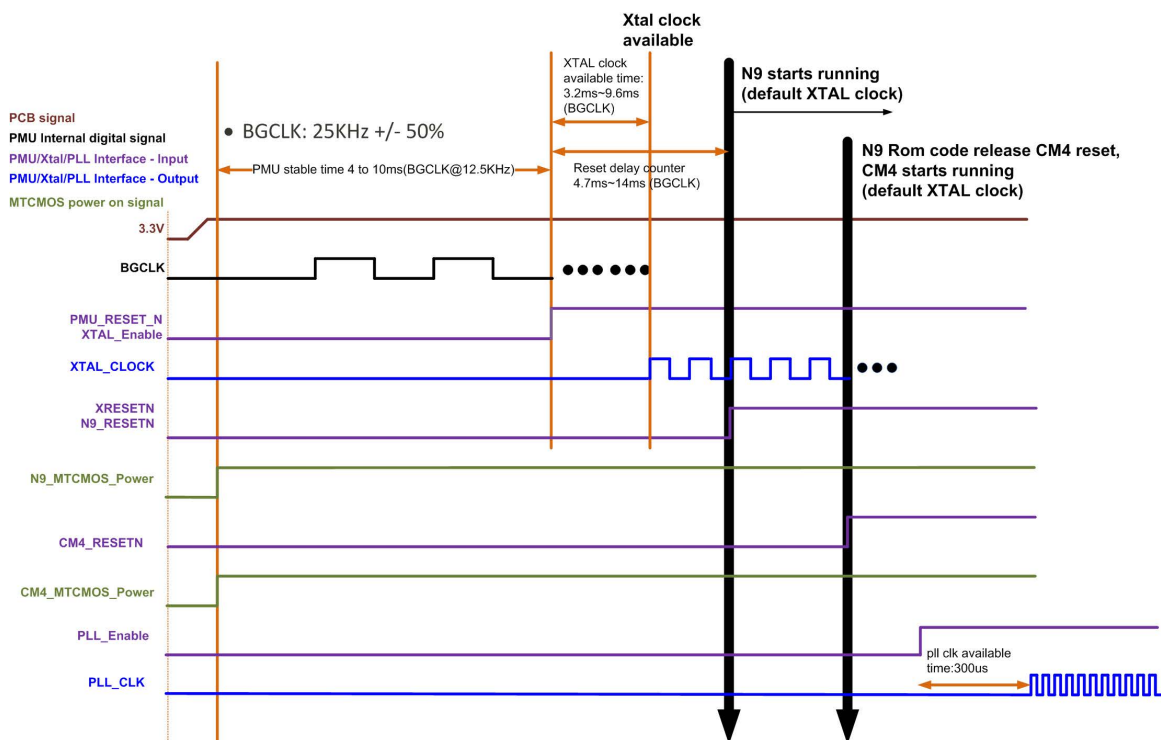


Figure 2-8. PMU Power-on Sequence

2.4.10.1 Power-on Reset (Cold Reset)

The power on reset sequence after chip power on is shown below.

- Step 1: N9 reset is de-asserted and boot from ROM (CM4 reset state is still asserted)
- Step 2: N9 sets up top configuration registers (such as PLL) and then de-asserts CM4 reset
- Step 3: CM4 boots from ROM while N9 polls the PDA (Patch Decryption Accelerator) status
- Step 4: CM4 fetch flash header (N9 FW download length information)
- Step 5: CM4 setup PDA and PDA address generator
- Step 6: PDA loads firmware from the flash to N9 IDLM

Step 7: N9 executes from IDLM after PDA completes and CM4 executes from Cache/Flash or TCM.

2.4.10.2 Watchdog Reset

Watchdog reset WDT_N9 is the watchdog timer for N9, and WDT_CM4 is the watchdog timer for CM4.

When the WDT event of WDT_N9 occurs, WDT_N9 has the capability to

- Reset N9 or issue an interrupt to N9.
- Issue an interrupt to CM4 (can be masked by CM4 if it is not required to be received).

When the WDT event of WDT_CM4 occurs, WDT_CM4 has the capability to

- Reset whole chip or reset CM4 only or issue an interrupt to CM4.
- Issue an interrupt to N9 (can be masked by N9 if it's not required to be received).

For both WDT_N9 and WDT_CM4, the WDT events can be triggered by time-out and software programming.

For both WDT_N9 and WDT_CM4, the WDT has the capability to reset the other CPU or issue an interrupt to the other CPU.

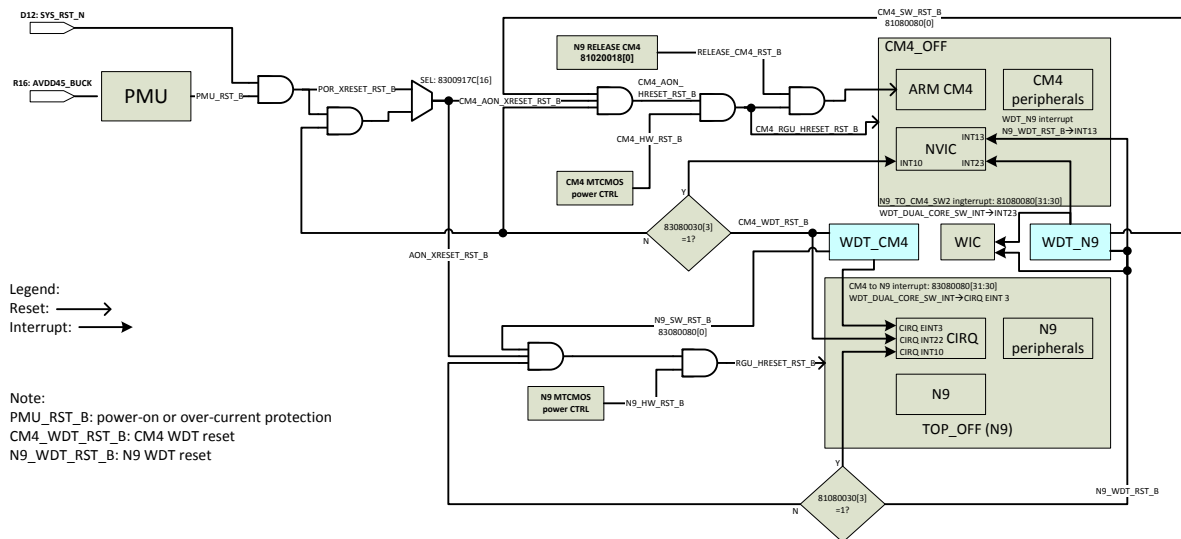


Figure 2-9. WDT Structure

2.4.10.3 Reset Scenarios

The definitions of the cold reset and the warm reset are shown below:

- Cold Reset: Power on reset and both RAM or peripheral devices will be initialized by firmware.
- Warm Reset: CPU is reset but RAM content is still retained (without firmware re-download). It's triggered by
 - Software reset: Software set WDT reset control register to reset CPU.
 - WDT reset: WDT expiration cause CPU to reset if enabled, otherwise interrupt.
 - Core reset: Reset by the other CPU (e.g. N9 to reset CM4 or CM4 to reset N9).
 - Wake-up from deep sleep mode: Reset by the MTCMOS power control.

2.4.10.4 Sleep/Wakeup sequence

The sleep/wakeup control sequence is shown in the diagram below.

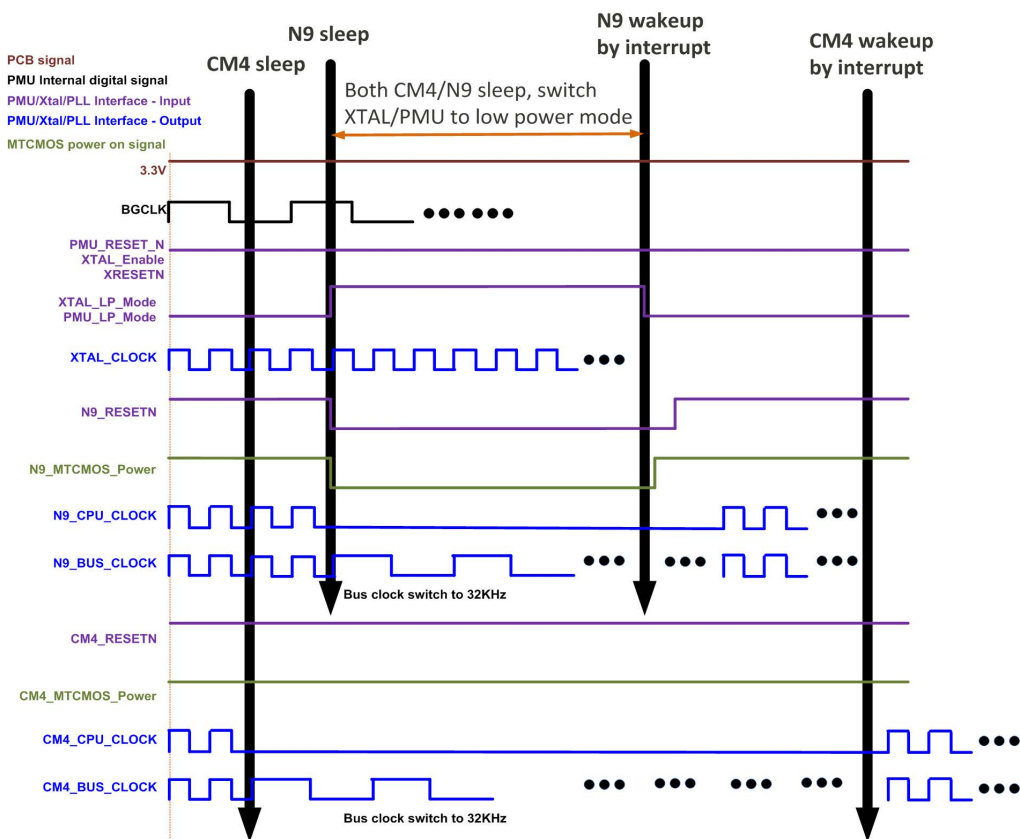


Figure 2-10. Sleep/Wakeup Sequence

2.4.11 Memory Map

The table below describes how the peripherals are mapped to the CM4 memory.

When the MCU performs a read transaction to an undefined address, the bus returns 0. When the MCU performs a write transaction to an undefined address, the bus regards it as an invalid transaction and does nothing. The memory space of 0x5040_0000 to 0x5FFF_FFFF is an undefined region and shall not be accessed.

The power domain is identified in the table. The hardware clock gating is associated with the power control. When the CPU power domain is in power-off mode, it implies that the clock is also gated.

The software clock gating control, identified in the table below, provides the way to disable the function and lower its power consumption when the function is not used.

Table 2-15. CM4 Memory Map

Start address	End address	Function	Power Domain	Software Clock gating control	Description
0x0000_0000	0x0000_FFFF	TCM ROM	CM4_OFF		Tightly Coupled ROM for CM4
0x0010_0000	0x0010_FFFF	TCM RAM0	CM4_OFF		Tightly Coupled RAM for CM4 (64KB)
0x0011_0000	0x0011_1FFF	TCM RAM1	CM4_OFF		Tightly Coupled RAM for CM4 (8KB)
0x0011_2000	0x0011_3FFF	TCM RAM2	CM4_OFF		Tightly Coupled RAM for CM4 (8KB)
0x0011_4000	0x0011_5FFF	TCM RAM3	CM4_OFF		Tightly Coupled RAM for CM4 (8KB)
0x0011_6000	0x0011_7FFF	TCM RAM4	CM4_OFF		Tightly Coupled RAM for CM4 (8KB)
0x1000_0000	0x1FFF_FFFF	Serial Flash CM4	CM4_OFF		Serial flash of CM4
0x2000_0000	0x2003_FFFF	SYSRAM_CM4	CM4_OFF		System RAM for CM4, 256Kbytes
0x2100_0000	0x2100_FFFF	SPI-S	CM4_OFF	0x8300_0200[21]	SPI slave
0x2200_0000	0x2200_FFFF	I2S/Audio	CM4_OFF	0x8300_0200[14]	I2S
0x2400_0000	0x2400_FFFF	SPI-M	CM4_OFF	0x8300_0200[22]	SPI master
0x2500_0000	0x2500_CFFF	SYSRAM_N9	TOP_OFF(N9)		System RAM for N9, 52Kbytes
0x3000_0000	0x3FFF_FFFF	Serial Flash CM4	CM4_OFF		Serial flash of CM4 through system bus
0x5000_0000	0x501F_FFFF	HIF_device	TOP_OFF(N9)		Host interface device controller
0x5020_0000	0x502F_FFFF	HIF_host_CM4	TOP_AON		Host interface host controller of Wi-Fi radio
0x5040_0000	0x5FFF_FFFF	(Undefined)			
0x6000_0000	0x6FFF_FFFF	WIFISYS	TOP_OFF(N9)	0x8000_0100[5]	Wi-Fi subsystem
0x7000_0000	0x70FF_FFFF	PDA DMA port			Patch Decryption Accelerator DMA slave
0x7800_0000	0x7800_FFFF	VFF access port	TOP_OFF(N9)		Virtual FIFO access ports of N9 DMA

Start address	End address	Function	Power Domain	Software Clock gating control	Description
0x7900_0000	0x7900_FFFF	VFF_CM4 access port	CM4_OFF	0x8300_0200[3]	Virtual FIFO access ports of CM4 DMA
0x8000_0000	0x800C_FFFF	APB0	TOP_OFF(N9)		APB bridge 0 (synchronous to N9)
0x8000_0000	0x8000_FFFF	CONFIG	TOP_OFF(N9)		N9 subsystem configuration
0x8001_0000	0x8001_FFFF	DMA	TOP_OFF(N9)		Generic DMA engine for N9
0x8002_0000	0x8002_FFFF	TOP_CFG_OFF	TOP_OFF(N9)		TOP_OFF(N9) power domain chip level configuration (GPIO, PINMUX, RF, CLK control)
0x8003_0000	0x8003_FFFF	UART/BTIF	TOP_OFF(N9)	0x8000_0100[6]	UART or Bluetooth host interface for N9
0x8005_0000	0x8005_FFFF	UART_PTA	TOP_OFF(N9)	0x8000_0100[11]	Inter-chip communication for PTA
0x8008_0000	0x8008_FFFF	AHB_MON	TOP_OFF(N9)	0x8000_0100[10]	AHB bus monitor
0x8009_0000	0x8009_FFFF	ACCLR	TOP_OFF(N9)	0x8000_0100[13]	Bluetooth audio Packet Loss Concealment accelerator
0x800A_0000	0x800A_FFFF	UART_DSN	TOP_OFF(N9)	0x8000_0100[7]	UART for N9 debug
0x800B_0000	0x800B_FFFF	SEC	TOP_OFF(N9)		Secure boot configuration
0x800C_0000	0x800C_FFFF	HIF	TOP_OFF(N9)		Host interface configuration
0x8100_0000	0x810C_FFFF	APB1	TOP_OFF(N9)		APB bridge 1 (synchronous to N9)
0x8100_0000	0x8100_FFFF	BTSYS	TOP_OFF(N9)	0x8000_0100[24]	Bluetooth subsystem
0x8102_0000	0x8102_FFFF	TOP_CFG_AON	TOP_AON		TOP_AON power domain chip level configuration (RGU, PINMUX, PLL, PMU, XTAL, CLK control)
0x8103_0000	0x8103_FFFF	DBG_CIRQ	TOP_AON		Debug interrupt controller for N9

Start address	End address	Function	Power Domain	Software Clock gating control	Description
0x8104_0000	0x8104_FFFF	CIRQ	TOP_AON		Interrupt controller for N9
0x8105_8000	0x8105_FFFF	GPT	TOP_AON		General Purpose Timer for N9
0x8106_0000	0x8106_FFFF	PTA	TOP_OFF(N9)	0x8000_0100[14]	Packet Traffic Arbitrator for Wi-Fi/Bluetooth coexistence
0x8107_0000	0x8107_FFFF	EFUSE_MAC	TOP_OFF(N9)	0x8000_0100[12]	Efuse controller
0x8108_0000	0x8108_FFFF	WDT	TOP_AON		Watchdog Timer for N9
0x8109_0000	0x8109_FFFF	PDA	TOP_OFF(N9)		Patch Decryption Accelerator
0x810A_0000	0x810A_FFFF	RDD	TOP_OFF(N9)	0x8000_0100[23]	Wi-Fi debug
0x810B_0000	0x810B_FFFF	BTSBC	TOP_OFF(N9)	0x8000_0100[15]	Bluetooth SBC accelerator
0x810C_0000	0x810C_FFFF	RBIST	TOP_OFF(N9)		RF BIST configuration
0x8300_0000	0x810C_FFFF	APB2	CM4_OFF		APB bridge 1 (synchronous to CM4)
0x8300_0000	0x8300_7FFF	CONFIG_CM4	CM4_OFF		System configuration for CM4
0x8300_8000	0x8300_BFFF	TOP_CFG_AON_CM4	TOP_AON		TOP_AON configuration
0x8300_C000	0x8300_EFFF	CONFIG_CM4_AON	TOP_AON		System configuration for CM4 in TOP_AON domain
0x8300_F000	0x8300_FFFF	SEC_TOP_CM4	CM4_OFF	0x8300_0200[0]	JTAG security for CM4
0x8301_0000	0x8301_FFFF	DMA_CM4	CM4_OFF	0x8300_0200[3]	Generic DMA engine for CM4
0x8302_0000	0x8302_FFFF	UART_DSN	CM4_OFF	0x8300_0200[4]	UART for CM4 debug
0x8303_0000	0x8303_FFFF	UART1	CM4_OFF	0x8300_0200[5]	UART 1 for CM4
0x8304_0000	0x8304_FFFF	UART2	CM4_OFF	0x8300_0200[6]	UART 2 for CM4
0x8305_0000	0x8305_FFFF	GPT_CM4	TOP_AON		General Purpose Timer for CM4

Start address	End address	Function	Power Domain	Software Clock gating control	Description
0x8306_0000	0x8306_FFFF	IrDA	CM4_OFF	0x8300_0200[8] 0x8300_0200[9]	IrDA
0x8307_0000	0x8307_FFFF	Serial flash	CM4_OFF	0x8300_0200[10]	Serial flash macro access
0x8308_0000	0x8308_FFFF	WDT_CM4	TOP_AON		Watchdog Timer for CM4
0x8309_0000	0x8309_FFFF	I2C_1	CM4_OFF	0x8300_0200[12] 0x8300_0200[23]	I2C 1
0x830A_0000	0x830A_FFFF	I2C_2	CM4_OFF	0x8300_0200[13] 0x8300_0200[24]	I2C 2
0x830B_0000	0x830B_0FFF	I2S	CM4_OFF	0x8300_0200[14]	I2S configuration
0x830C_0000	0x830C_FFFF	RTC	RTC		Real time clock
0x830D_0000	0x830D_FFFF	AUXADC	CM4_OFF	0x8300_0200[16]	Auxiliary ADC configuration
0x830E_0000	0x830E_FFFF	BTIF	CM4_OFF	0x8300_0200[17]	Host Interface for Bluetooth radio
0x830F_0000	0x830F_FFFF	Crypto	CM4_OFF	0x8300_0200[18]	Crypto engine
0xA000_0000	0xAFFF_FFFF	PSE	CM4_OFF		Packet switch engine memory
0xE000_E000	0xE000_EFFF	NVIC, SYSTICK, FPU	CM4_OFF		Nested vectored interrupt controller System Control Space (SYSTICK) Floating-point unit

2.4.12 SYSRAM_CM4

SYSRAM, the internal SRAM, is mapped on the system bus interface of Cortex M4. M4 can carry out instruction fetches and data accesses to the SYSRAM.

SYSRAM is the internal SRAM that the DMA engine can access. It can be used as a GDMA or VFIFO buffer, the source and the destination of GDMA controller, for memory-to-memory transfer as well the transfer between memory and peripherals.

2.4.13 Crypto engine

The crypto engine supports

- AES, DES, and 3DES encryption and decryption engine.
- SHA256, SHA512 and MD5 hash engines.

2.5 Peripherals

Several peripheral are multiplexed GPIOs. MT7697 has two dedicated UART interfaces with flow control, one dedicated I2C interface, and one dedicated IrDA interface.

MT7697 also has the 2nd I2C interface, the SPI slave interface, the I2S interface, and the SPI master interface, but only 2 of the above interfaces can be effective at a time.

The section describes the function of all the peripherals.

2.5.1 GPIO Interface

2.5.1.1 GPIO Function

There are two types of GPIO (General purpose IO) designs in MT7697: GPIO and AGPIO.

Floating-well design is used in GPIO and AGPIO. It prevents potential leakage problem when the DVDD33 power supply is not enabled but the pin input is pulled up to 3.3V source.

MT7697 offers GPIO, each with the following configuration options:

- Input / Output mode
- Slew rate control
- Schmitt trigger hysteresis control
- Input mode: Floating (Hi-Z), pull-up, or pull-down
- Output mode: Active driving, or open drain
- Pull up/down control. The pull-up and pull-down resistance is 75K Ω with $\pm 20\%$ variation over PVT condition
- Driving strength: 4mA, 8mA, 12mA, 16mA
- Input and output duty cycle tuning

AGPIO Function Table		
G	E Function	
0	0	Analog Function (IO <- -> AIO)
0	1	Analog Function (IO <- -> AIO)
1	0	Digital Function (IO -----> O)
1	1	Digital Function (IO <- - I) (4 – 16 mA Driving)

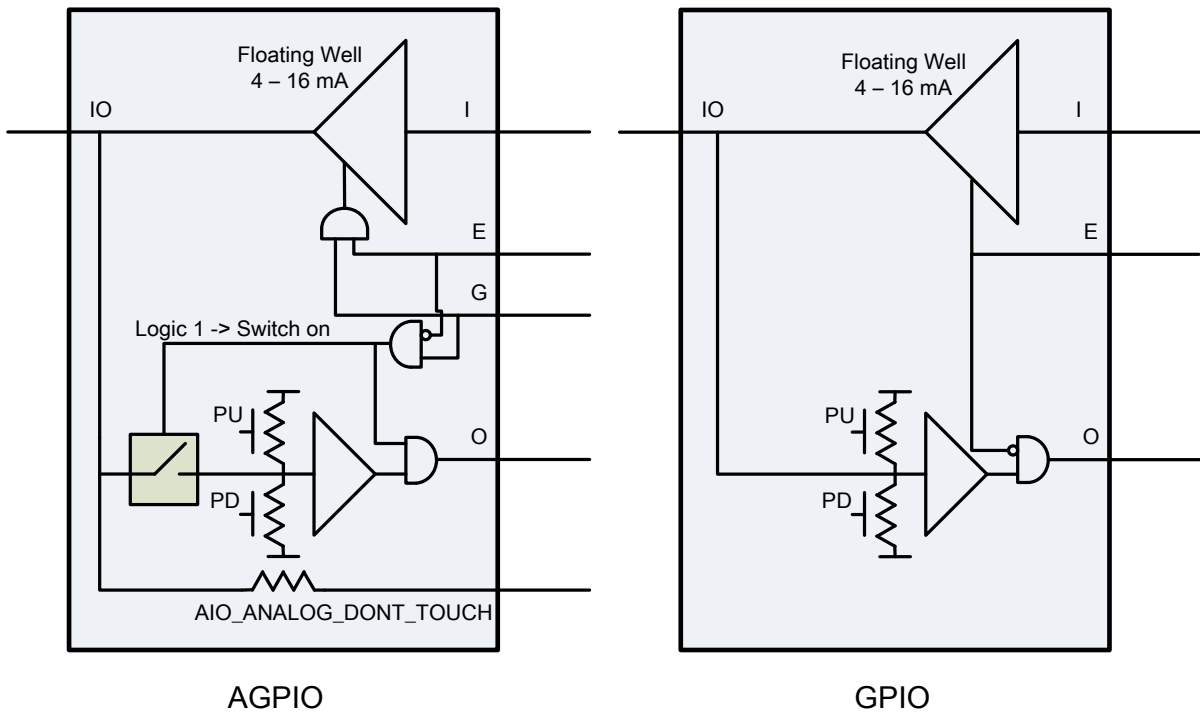


Figure 2-11. AGPIO/GPIO Block Diagram (Left: AGPIO; Right: GPIO)

The digital IO AGPIO function is equivalent to GPIO as shown above. A dedicated internal control signal is used to select between the digital and analog functions. The IOs are multiplexed with 16 channels ADC.

Output Signal Multiplexing

Function-[9:1]-AON and Function-[9:0] can all be output to PINX by setting `pinx_pinmux_aon_sel` and `pinx_pinmux_off_sel`, as shown in Figure 2-12 below. Function-[9:1]-AON signals are part of TOP_AON domain and Function-[9:0] signals are part of TOP_OFF (N9) domain. The output of the pad is enabled through E and G pad controls which require 2'b11 for digital output mode.

For a specific pin there could be only a limited number of functions available, these functions are mapped anywhere to the different inputs of the muxes (not always in an incremental scheme).

TOP_AON domain means the circuit is always powered on when PMU supplies the power. TOP_OFF (N9) domain means the N9 related circuit is powered off in some scenarios when PMU supplies the power.

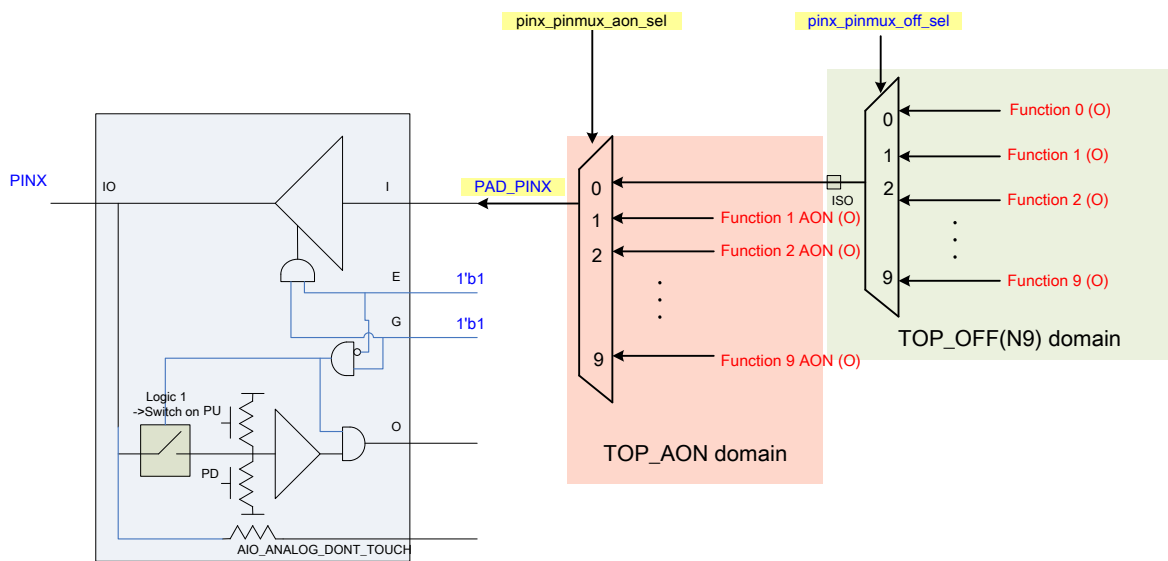


Figure 2-12. AGPIO Configured as Output Multiplexing

Input Signal Multiplexing

Figure 2-13 below shows that PINX is the source of Function-AON-0, while PINX and PINY can both be the input source for Function-1. The (E, G) setting for both IO is 2'b01 for digital input mode.

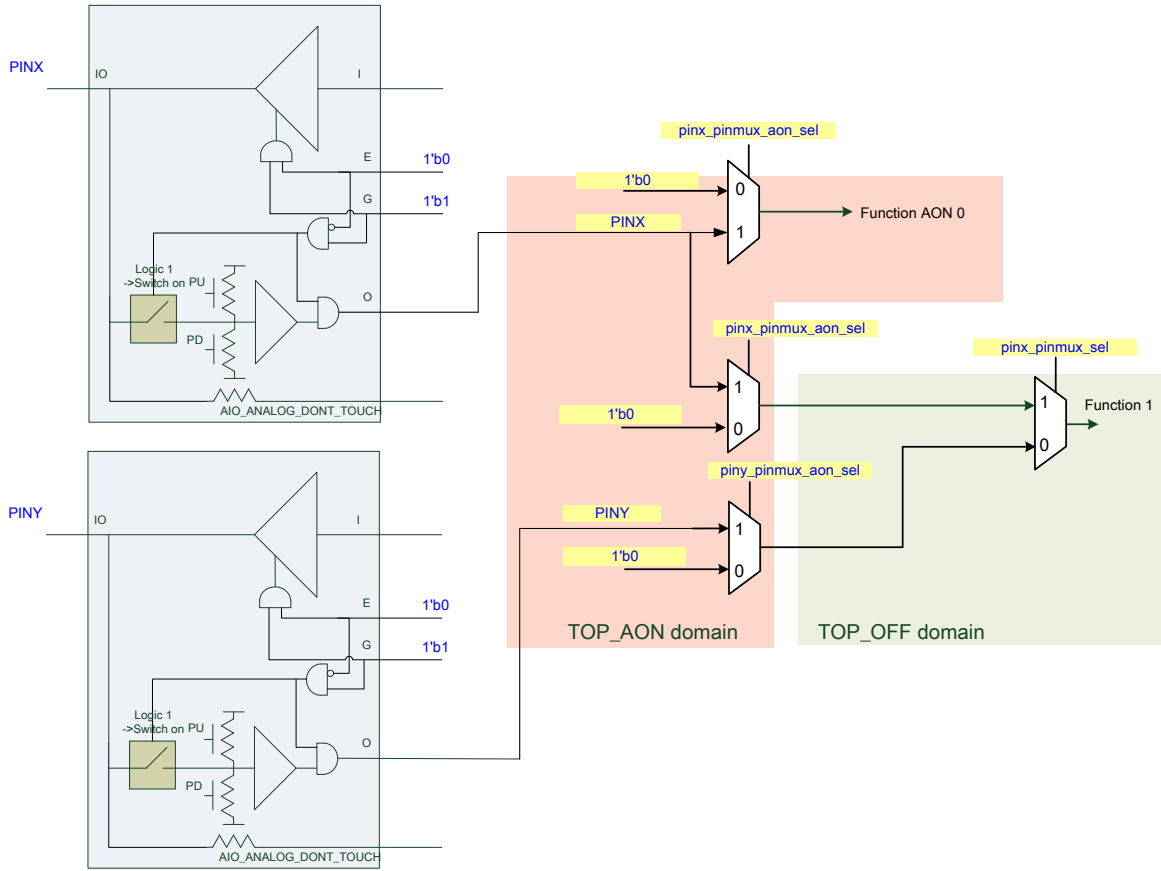


Figure 2-13. AGPIO Configured as Input Multiplexing

Input / Output / Analog Signal Multiplexing

This figure below shows how function-0, function-1 and Analog-function share the same IO (PINX) by configuring (E, G) pair internally. G is controlled in off domain.

Table 2-16. Functional Description of AGPIO

(G,E) value	2'b11	2'b10	2'b0x
Function	PINX=Function-0	Function-1=PINX	Analog-function=PINX
	(output mode)	(input mode)	(analog mode)

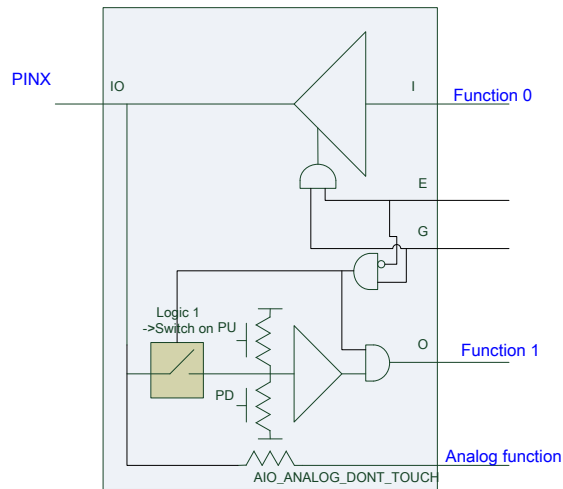


Figure 2-14. AGPIO Configured as Input, Output, or Analog Mode

Open Drain Mode

The GPIO can be configured as open drain mode by assigning I=1'b0, G=1'b1 and E=Function-0.

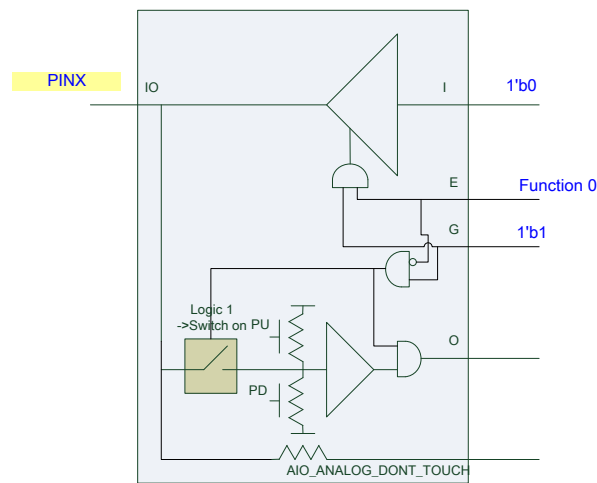


Figure 2-15. GPIO Configured as Open Drain Mode

2.5.2 UART Interface

MT7697 has two UART interfaces. The UART has M16C450 and M16550A modes of operation, which are compatible with a range of standard software drivers. MT7697 supports UART with configurable BAUD rates from 9.6Kbps, 19.2Kbps, 38.4Kbps, 115.2Kbps, and 921.6Kbps.

2.5.3 I2C Serial Interface

MT7697 features two I2C serial interface master controllers. The two signals of I2C channel 0 are I2CO_CLK and I2CO_DATA.

- I2CO_CLK is a clock signal that is driven by the master.
- I2CO_DATA is a bi-directional data signal that can be driven by either the master or the slave. It supports the clock rate of 50, 100, 200, and 400 KHz.
- I2C channel 1 supports the same feature as channel 0.

2.5.4 Auxiliary ADC function

MT7697 features one auxiliary ADC function. The ADC function contains a 4-channel analog switch, a single-end input asynchronous 12-bit SAR (Successive Approximation Register) ADC, and a digital averaging function. The digital averaging function can perform on-the-fly averaging function of 1/2/4/8/16/32/64 points. The ADC features the dithering function to enhance the DNL performance. The ADC uses an external VREF20 as a reference voltage.

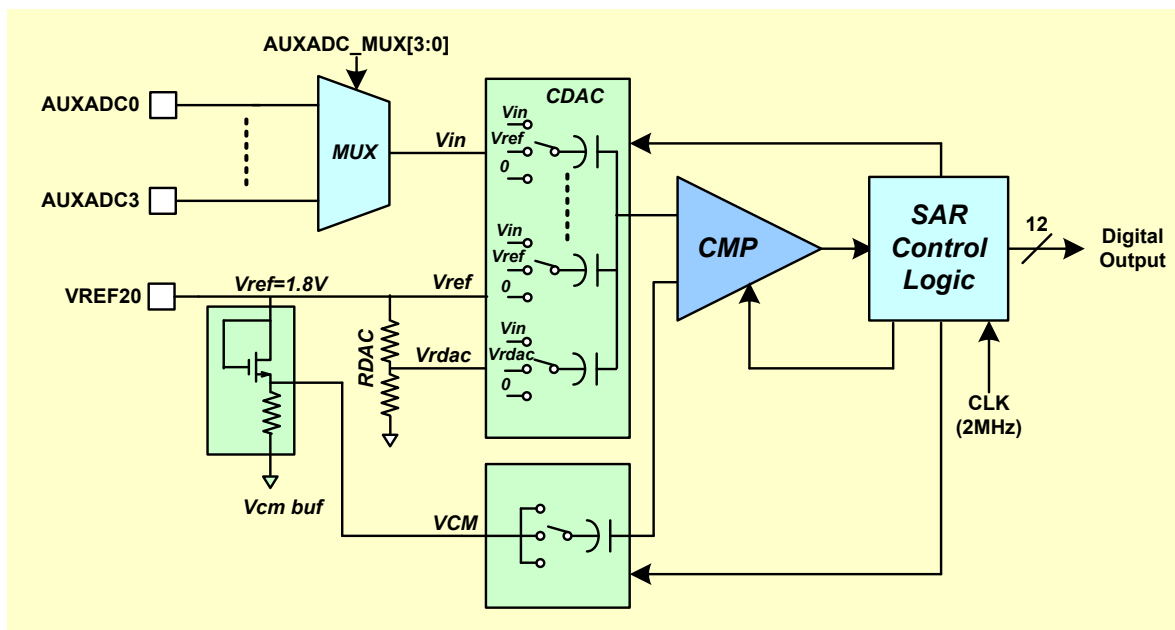


Figure 2-16. Auxiliary ADC Block Diagram (Analog Part)

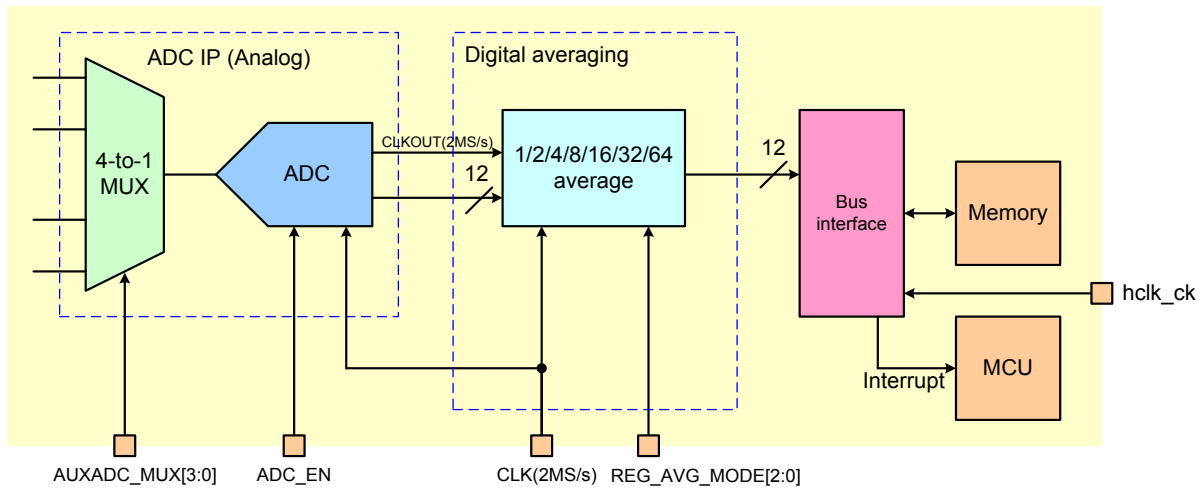


Figure 2-17. Auxiliary ADC Block Diagram

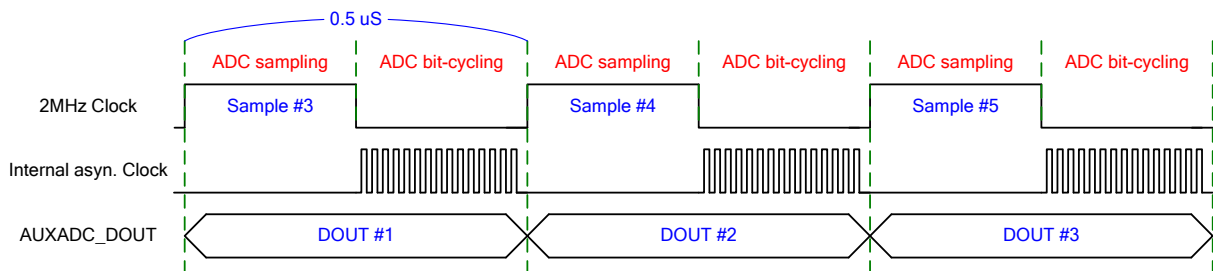


Figure 2-18. Auxiliary ADC Clock Timing Diagram

Auxiliary ADC Features:

- Input channel number: 4 channels
- Sampling and output data rate: 2MS/s
- DNL without dithering and averaging: $<\pm 2\text{LSB}$
- DNL with dithering and averaging: $<\pm 1\text{LSB}$
- Dithering function: 16 levels with step size of 4LSB.

2.5.5 SPI Master Interface

MT7697 features one SPI master controller. It is used as an extension interface to control the peripheral device on expansion port. The SPI master controller supports the clock rates of 0.25, 0.5, 1, 2, 4, 6, 8, 10, and 12MHz. It supports two options of clock polarity (CPOL) and two options of initial clock phase (CPHA). SPI pins are multiplexed with I2S pins.

Table 2-17. SPI Pin Description

Signal Name	Signal Description	Direction
CS	Chip select	Output
SCK	Serial clock	Output
MISO	Master in, Slave out	Input
MOSI	Master out, Slave in	Output

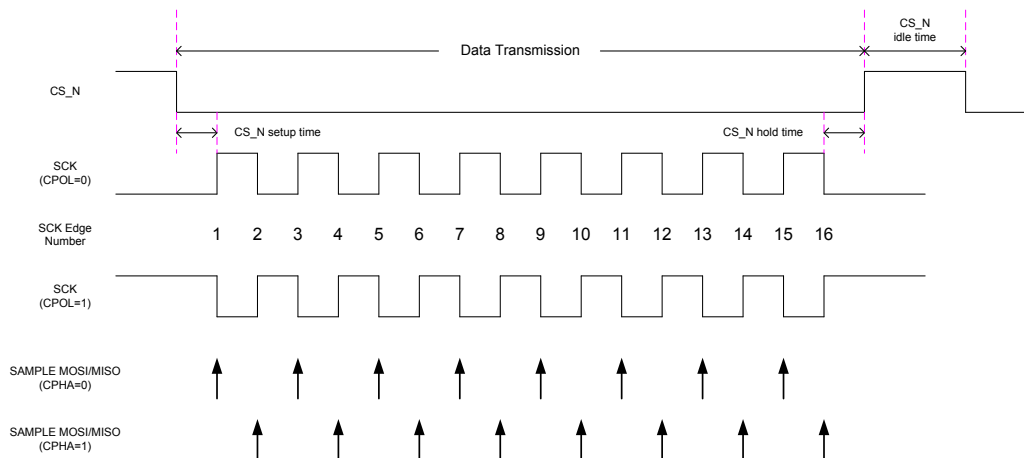


Figure 2-19. SPI Timing Diagram

2.5.6 SPI Slave Interface

2.5.7 I2S Interface

MT7697 features one I2S interface, which is used to connect to an external audio codec. The I2S interface can support the I2S slave mode only. The five I2S signals are shown below. The I2S_MLK clock frequency is 16MHz.

Table 2-18. I2S Pin Description

Signal Name	Signal Description	Direction (Slave Mode)
I2S_MCLK	The base clock of the function.	Output
I2S_BCLK	The bit clock of the interface	Input
I2S_FS (LRCLK)	The left/right word select line of the interface	Input
I2S_TX	Digital audio output	Output
I2S_RX	Digital audio input	Input

MT7697 supplies the MCLK of 16MHz. The external CODEC generates BCLK and LRCLK from MCLK. When configured as the I2S slave mode, the I2S interface can support two modes.

Table 2-19. I2S Slave Mode

Slave Mode	Bit Width	Input Sample (Uplink)	Output Sample (Downlink)	BCLK (Input)	FS (Input)
Mode 1	16b	16KHz, mono	16KHz, mono	512KHz	16KHz
Mode 2	16b	24KHz, mono	24KHz, mono	768KHz	24KHz

The mono data is transferred across the I2S bus as left channel information.

In all of the modes above, when the input data is mono, the data of interest is transferred across the I2S bus on the left channel.

The I2S pins are multiplexed with SPI pins.

The signal waveform of I2S is shown below.

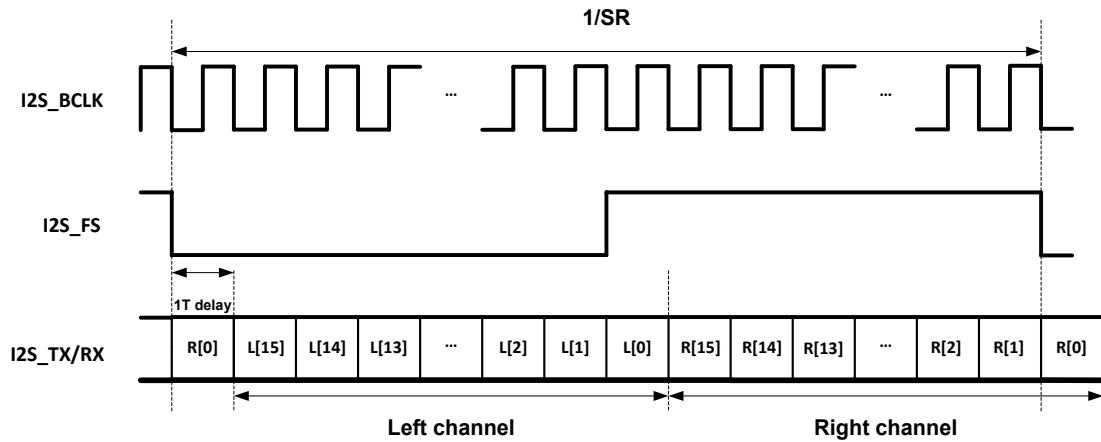


Figure 2-20. I2S Signal Waveform

2.5.8 Pulse Width Modulation (PWM)

MT7697 features 28 generic PWMs to generate pulse sequences with programmable frequency and duration for LCD, vibrators, and other devices. The PMU features three configurable pattern options.

Table 2-20. PWM Modes

Mode	Description	Waveform
1	Basic PWM: LED ON time (duration) and LED OFF time (duration) are configurable.	
2	Two-State PWM: There are two configurable states (S0 and S1) for PWM LED.	
3	Two-State replay mode: User can set replay mode with specified S1_Lasting_Time. PWM LED would act as [S0→S1→S0→S1→S0...] with period time of (S0_Lasting_Time +	

Mode	Description	Waveform
	S1_Lasting_Time)	

2.5.9 IrDA

IrDA TX module supports consumer IR protocols including NEC, RC-5, RC-6, and the software-based pulse-width mode. IrDA RX module supports protocols including RC-5 and pulse-width detection mode.

2.6 Radio MCU Subsystem

2.6.1 CPU

MT7697 features 32-bit CPU N9, with the following features:

- 5-stage pipeline with extensive clock-gating
- Dynamic branch prediction with BTB
- 16/32-bit mixed instruction format
- Multiply-accumulate and multiply-subtract instructions
- Instructions optimized for audio applications
- Instruction and data local memory
- JTAG based debug interface
- Programmable data endian control

2.6.2 RAM/ROM

The Radio MCU subsystem features ILM (Instruction Local Memory), DLM (Data Local Memory), and the SYSRAM. The ROM code is in ILM.

2.6.3 Memory map

The table below describes how the peripherals are mapped to the memory space in Radio MCU subsystem.

When the MCU performs a read transaction to an undefined address, the bus returns 0. When the MCU performs a write transaction to an undefined address, the bus regards it as an invalid transaction and does nothing.

Table 2-21. N9 Memory Map

Start address	End address	Function	Description
0x0000_0000	0x000C_FFFF	ILM ROM	Instruction local memory ROM for N9
0x000D_0000	0x0011_FFFF	ILM RAM	Instruction local memory RAM for N9

Start address	End address	Function	Description
0x0200_0000	0x0200_021C	Patch & CR	N9 ROM patch engine
0x0209_0000	0x020C_1FFF	DLM RAM	Data local memory for N9
0x0040_0000	0x0040_CFFF	SYSRAM N9	System RAM for N9
0x2000_0000	0x2003_FFFF	SYSRAM CM4	System RAM for CM4 (256KB)
0x2100_0000	0x2100_FFFF	SPI-S	SPI slave
0x2200_0000	0x2200_FFFF	I2S/Audio	I2S
0x2400_0000	0x2400_FFFF	(Reserved)	
0x3000_0000	0x3FFF_FFFF	Serial Flash CM4	Serial flash controller of CM4
0x5000_0000	0x501F_FFFF	HIF_device	Host interface device controller
0x5020_0000	0x502F_FFFF	HIF_host_CM4	Host interface host controller of Wi-Fi radio
0x6000_0000	0x6FFF_FFFF	WIFISYS	Wi-Fi subsystem
0x7000_0000	0x70FF_FFFF	PDA DMA port	Patch Decryption Accelerator DMA slave
0x7800_0000	0x7800_0000	VFF access port0	Virtual FIFO access port 0 of N9 DMA
0x7800_0100	0x7800_0100	VFF access port1	Virtual FIFO access port 1 of N9 DMA
0x7900_0000	0x7900_FFFF	VFF_CM4 access port	Virtual FIFO access ports of CM4 DMA
0x8000_0000	0x800C_FFFF	APB0	APB bridge 0 (synchronous to N9)
0x8000_0000	0x8000_FFFF	CONFIG	N9 subsystem configuration
0x8001_0000	0x8001_FFFF	DMA	Generic DMA engine for N9
0x8002_0000	0x8002_FFFF	TOP_CFG_OFF	TOP_OFF(N9) power domain chip level configuration (GPIO, PINMUX, RF, PLL, CLK control)
0x8003_0000	0x8003_FFFF	UART/BTIF	UART or Bluetooth host interface for N9
0x8005_0000	0x8005_FFFF	UART_PTA	Inter-chip communication for PTA
0x8008_0000	0x8008_FFFF	AHB_MON	AHB bus monitor
0x8009_0000	0x8009_FFFF	ACCLR	Bluetooth audio Packet Loss Concealment accelerator
0x800A_0000	0x800A_FFFF	UART_DSN	UART for N9 debug
0x800B_0000	0x800B_FFFF	SEC	Secure boot configuration
0x800C_0000	0x800C_FFFF	HIF	Host interface configuration
0x8100_0000	0x810C_FFFF	APB1	APB bridge 1 (synchronous to N9)
0x8100_0000	0x8100_FFFF	BTSYS	Bluetooth subsystem
0x8102_0000	0x8102_FFFF	TOP_CFG_AON	TOP_AON power domain chip level configuration (RGU, PINMUX, PMU, XTAL, CLK)

Start address	End address	Function	Description
			control)
0x8103_0000	0x8103_FFFF	DBG_CIRQ	Debug interrupt controller for N9
0x8104_0000	0x8104_FFFF	CIRQ	Interrupt controller for N9
0x8105_8000	0x8105_FFFF	GPT	General Purpose Timer for N9
0x8106_0000	0x8106_FFFF	PTA	Packet Traffic Arbitrator for Wi-Fi/Bluetooth coexistence
0x8107_0000	0x8107_FFFF	EFUSE	Efuse controller
0x8108_0000	0x8108_FFFF	WDT	Watchdog Timer for N9
0x8109_0000	0x8109_FFFF	PDA	Patch Decryption Accelerator
0x810A_0000	0x810A_FFFF	RDD	Wi-Fi debug
0x810B_0000	0x810B_FFFF	BTSBC	Bluetooth SBC accelerator
0x810C_0000	0x810C_FFFF	RBIST	RF BIST configuration
0x8300_0000	0x8300_FFFF	APB2	APB bridge 1 (synchronous to CM4)
0x8300_0000	0x8300_FFFF	CONFIG_CM4	System configuration for CM4
0x8301_0000	0x8301_FFFF	DMA_CM4	Generic DMA engine for CM4
0x8302_0000	0x8302_FFFF	UART_DSN	UART for CM4 debug
0x8303_0000	0x8303_FFFF	UART1	UART 1 for CM4
0x8304_0000	0x8304_FFFF	UART2	UART 2 for CM4
0x8305_0000	0x8305_FFFF	GPT_CM4	General Purpose Timer for CM4
0x8306_0000	0x8306_FFFF	IrDA	IrDA
0x8307_0000	0x8307_FFFF	Serial flash	Serial flash macro access
0x8308_0000	0x8308_FFFF	WDT_CM4	Watchdog Timer for CM4
0x8309_0000	0x8309_FFFF	I2C_1	I2C 1
0x830A_0000	0x830A_FFFF	I2C_2	I2C 2
0x830B_0000	0x830B_FFFF	I2S	I2S configuration
0x830D_0000	0x830D_FFFF	AUXADC	Auxiliary ADC configuration
0x830E_0000	0x830E_FFFF	BTIF	Host Interface for Bluetooth radio
0x830F_0000	0x830F_FFFF	Crypto	Crypto engine
0xA000_0000	0xAFFF_FFFF	PSE	Packet switch engine memory

2.6.4 N9 Bus Fabric

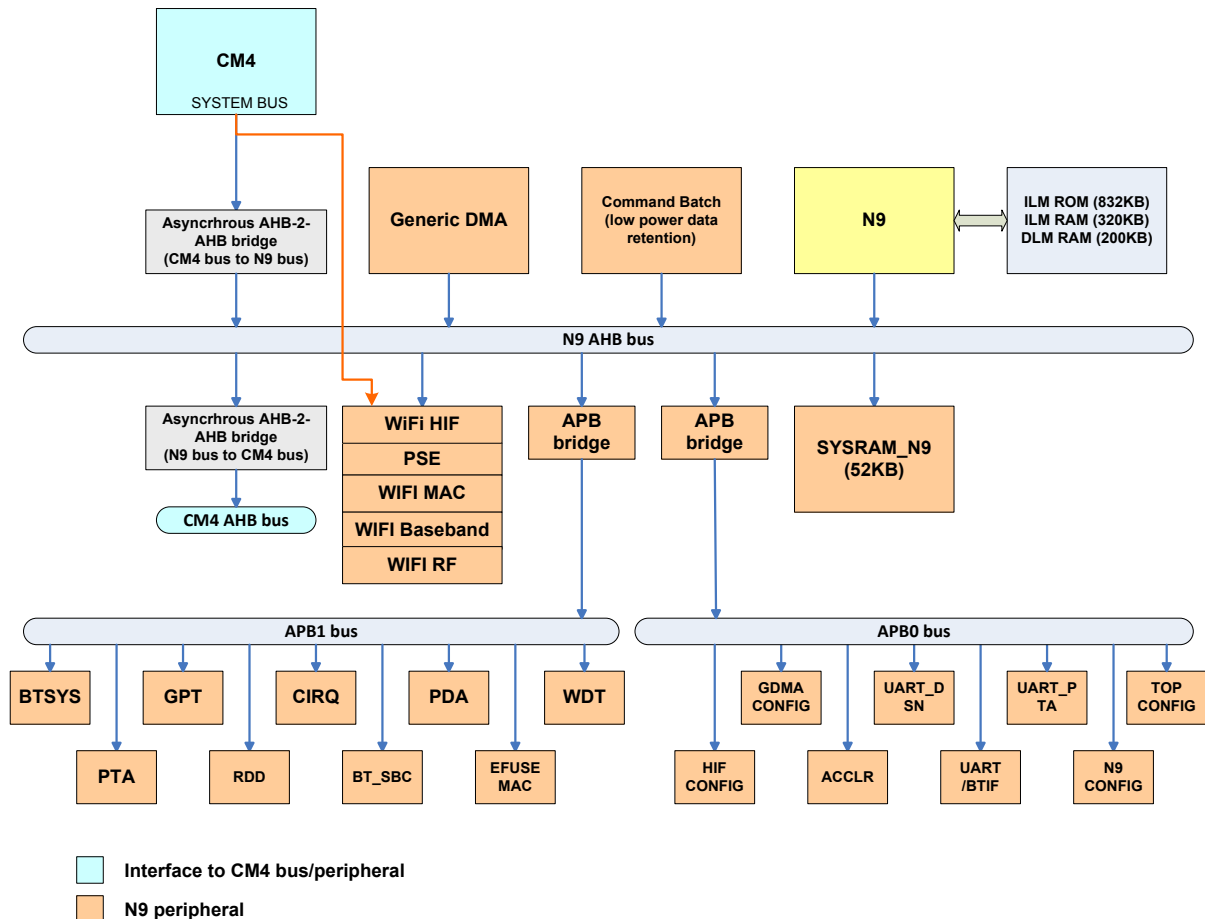


Figure 2-21. N9 Bus Fabric

Functional description:

- Command batch: Used to save/restore the critical CR and memory data when entering and leaving the low power mode.
- Wi-Fi HIF: The host control and data interface from N9 to Wi-Fi subsystem.
- Wi-Fi PSE: The Packet switch engine used to transfer packet from N9 to Wi-Fi MAC/Radio or from CM4 to Wi-Fi MAC/Radio, and vice versa.
- PDA: Packet Decryption Agent, used to download firmware and decipher the firmware which is encrypted to avoid eavesdrop.
- PTA: Packet Traffic Arbitration, used to do the traffic arbitration of Wi-Fi and Bluetooth when the two radios are transmitting and receiving at the same time.
- RDD: The Wi-Fi debug function.
- BT_SBC: The hardware accelerating engine for Bluetooth audio codec.
- EFUSE: The Efuse macro used for the configuration of Wi-Fi/Bluetooth MAC and Radio.
- ACCLR: The hardware accelerating engine for Bluetooth Packet Loss Concealment.

2.6.5 CIRQ

N9 subsystem uses the interrupt controller CIRQ to control the source selection, mask, edge/level sensitivity, and software enabling for internal interrupts, as well as the mask and the edge/level sensitivity for external interrupts.

CIRQ also integrates the de-bounce circuit for external interrupts.

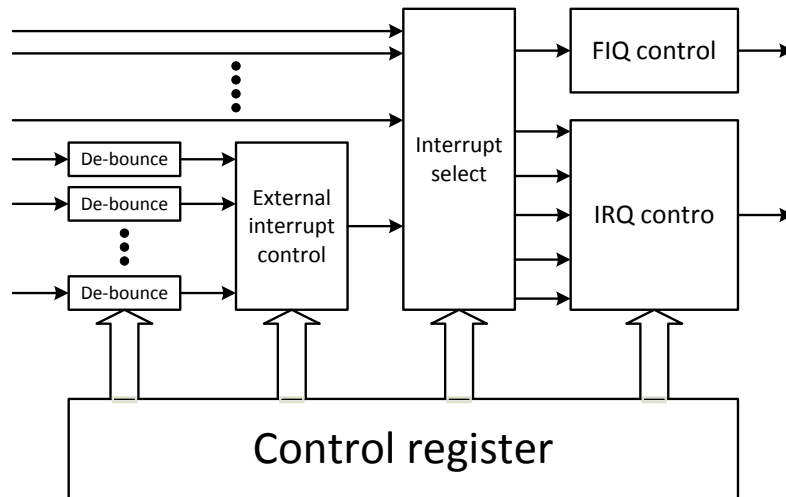


Figure 2-22. N9 interrupt controller

2.6.5.1 Interrupt sources

The tables below lists the interrupt sources of internal and external interrupts.

There are totally 23 interrupts and 14 external interrupts.

The power domain/subsystem lists the power domain and the subsystem from which the interrupt is generated.

IRQ No.	Interrupt source	Power domain /subsystem	External interrupt	Wake-up capability (1)	De-bounce	Description
INT0	UART	TOP_OFF(N9)/MCUSYS				UART/BTIF module
INT1	DMA	TOP_OFF(N9)/MCUSYS				Generic DMA in N9 subsystem
INT2	HIFSYS	TOP_AON/HIF				WIFI_HIF(SDIO)
INT3	BT_TIMCON	TOP_AON/BTSYS				Bluetooth TIMCON module
INT4	THERM	TOP_OFF(N9)				Thermometer
INT5	(Reserved)					
INT6	WIFI	WF_OFF				Wi-Fi subsystem
INT7	ICAP	TOP_OFF(N9)/MCUSYS				Internal capture in RBIST module

IRQ No.	Interrupt source	Power domain /subsystem	External interrupt	Wake-up capability (1)	De-bounce	Description
INT8	EINT	TOP_AON/MCUSYS				External interrupt
INT9	(Reserved)					
INT10	WDT_N9	TOP_AON/MCUSYS				Watch dog timer in N9 subsystem
INT11	AHB_MONITOR	TOP_OFF(N9)/MCUSYS				AHB monitor
INT12	(Reserved)					
INT13	PLC_ACCLR	TOP_OFF(N9)/MCUSYS				Packet Loss Concealment accelerator
INT14	(Reserved)					
INT15	PSE	WF_OFF/PSE				Packet switch engine
INT16	MSBC	TOP_OFF(N9)/MCUSYS				Bluetooth SBC CODEC accelerator
INT17	HIFSYS	TOP_OFF(N9)/HIFSYS				HIF subsystem
INT18	UART_PTA *	TOP_OFF(N9)/MCUSYS				UART_PTA module
INT19	PTA *	TOP_OFF(N9)/MCUSYS				PTA module
INT20	CMBT	TOP_OFF(N9)				Command batch module
INT21	GPT3	TOP_AON/MCUSYS				General purpose timer module
INT22	WDT_CM4	TOP_AON/MCUSYS_CM4				CM4 WDT interrupt N9
EINT0	UART_RX	TOP_AON	V	V	Available	Wake up from UART
EINT1	(Reserved)		V	V	Available	
EINT2	HIFSYS	TOP_AON/HIF	V	V	Available	WIFI_HIF (SDIO)
EINT3	CM4_TO_N9_SW	TOP_AON/MCUSYS_CM4	V	V	Available	CM4 SW interrupt N9 83080080[31:30] SW_INT
EINT4	Bluetooth	TOP_AON/BTSYS	V	V	Available	Wake up from Bluetooth
EINT5	PCIE *	TOP_OFF(N9)/HIFSYS	V	V	Available	Wake up from PCIe
EINT6	GPT	TOP_AON/MCUSYS	V	V	Available	General purpose timer module (GPT0 timer and GPT1 timer)
EINT7	External interrupt	TOP_AON	V	V	Available	External interrupt Pin: GPIO58
EINT8	External interrupt	TOP_AON	V	V	Available	External interrupt Pin: GPIO57
EINT9	External interrupt	TOP_AON	V	V	Available	External interrupt Pin: GPIO30
EINT10	(Reserved)		V	V	Available	
EINT11	External interrupt	TOP_AON	V	V	Available	External interrupt Pin: GPIO38
EINT12	External interrupt	TOP_AON	V	V	Available	External interrupt Pin: GPIO39
EINT13	CM4_TO_N9_BTIF_WAKEUP	TOP_AON	V	V	Available	CM4 to N9 BTIF wake-up 830E0064[0] BTIF_WAK

*: Not used for MT7697

Note 1; Capable to wake up N9 when N9 is in sleep mode.

2.7 Wi-Fi Subsystem

2.7.1 Wi-Fi MAC

MT7697 MAC supports the following features:

- Supports all data rates of 802.11g including 6, 9, 12, 18, 24, 36, 48, and 54Mbps
- Supports short GI and all data rates of 802.11n including MCS0 to MCS7
- 802.11 to 802.3 header translation offload
- RX TCP/UDP/IP checksum offload
- Supports multiple concurrent clients as an access point
- Supports multiple concurrent clients as a repeater
- Aggregate MPDU RX (de-aggregation) and TX (aggregation) support
- Transmits beamforming as a beamformee
- Transmits rate adaptation
- Transmits power control
- Security
- 64-bit WEP (WEP-40) and 128-bit WEP (WEP-104) encryption with hardware TKIP and CKIP processing
- AES-CCMP hardware processing
- SMS4-WPI (WAPI) hardware processing

2.7.2 WLAN Baseband

MT7697 baseband supports the following features:

- 20 and 40MHz channels
- MCS0-7 (BPSK, $r=1/2$ through 64QAM, $r=5/6$)
- Short Guard Interval
- STBC support
- Low Density Parity check (LDPC) coding
- Support digital pre-distortion to enhance PA performance
- Smoothing (channel estimation) extension to MIMO case

2.7.3 WLAN RF

MT7697 RF supports the following features:

- Integrated 2.4GHzPA and LNA, and T/R switch
- Support frequency band
- 2400-2497MHz
- Support RX antenna diversity for both 2.4GHz band to eliminate the requirement of an external SPDT

2.8 Bluetooth Subsystem

MT7697 Bluetooth supports the following features:

- Bluetooth v4.2 + LE compliance

- Bluetooth and Bluetooth low energy dual mode
- Single-ended, RF port with integrated Balun and T/R switch
- Integrated high efficiency PA
- Baseband and radio BDR and EDR packet types: 1Mbps (GFSK), 2Mbps ($\pi/4$ -DQPSK), and 3Mbps (8PSK).
- Fully functional Bluetooth baseband: AFH, forward error correction, header error control, access code correlation, CRC, whitening.
- Standard pairing, authentication, link key, and encryption operation.
- Standard power saving mechanisms: sniff mode and sniff-subrating.
- Interlaced scan for faster connection setup
- Full master and slave piconet support
- Up to seven simultaneous active ACL connections with background inquiry and page scan
- Scatternet support
- Channel quality driven data rate control

2.9 RTC

MT7697 features one RTC (Real Time Clock) module. The clock source is the 32.768 KHz Crystal or an external clock source. RTC has built in an accurate timer to wake up the system when it expires.

RTC uses a different power rail from PMU. In the hibernate mode, the PMU is turned off while the RTC module is remained powered on. The RTC module only consumes 3uA in hibernate mode.

RTC has a dedicated PMU control pin PMU_EN_RTC (pin 23) used to turn on the power to the chip when the RTC timer expires and turn off the power to the chip when it intends to enter the hibernate mode.

3 Radio Characteristics

3.1 Wi-Fi Radio Characteristics

3.1.1 Wi-Fi RF Block Diagram

Front-end loss with external Balun (2.4GHz band): 2.4GHz band insertion loss is 2dB.

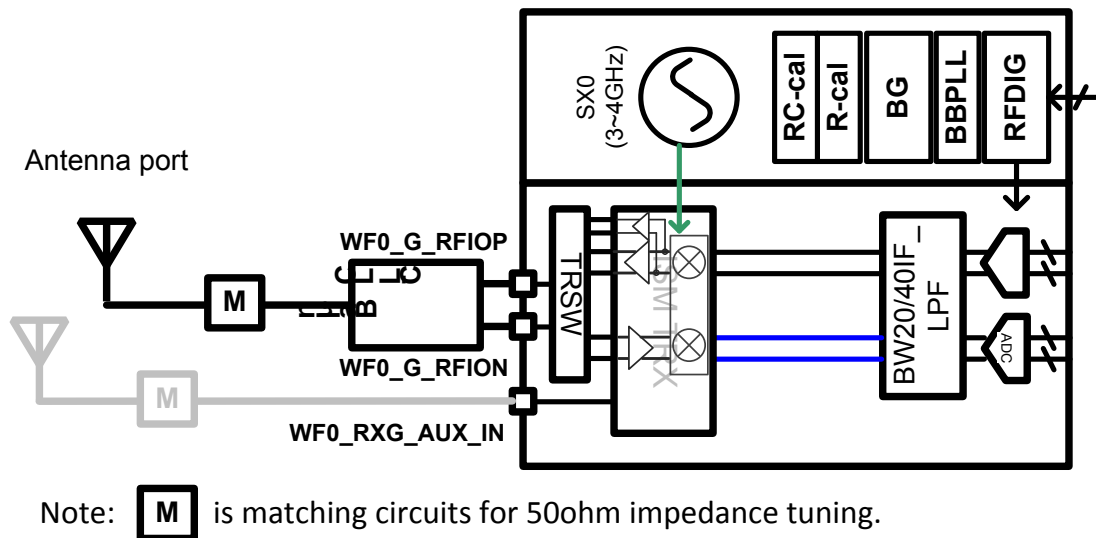


Figure 3-1. 2.4GHz RF Block Diagram

3.1.2 Wi-Fi 2.4GHz Band RF Receiver Specifications

The specifications noted in the table below is measured at the antenna port, which includes the front-end loss.

Table 3-1. 2.4GHz RF Receiver Specification

Parameter	Description	Performance			
		MIN	TYP	MAX	Unit
Frequency range	Center channel frequency	2412		2484	MHz
RX sensitivity	1 Mbps CCK	-	-96.4	-	dBm
	2 Mbps CCK	-	-93.4	-	dBm
	5.5 Mbps CCK	-	-91.4	-	dBm
	11 Mbps CCK	-	-88.4	-	dBm

Parameter	Description	Performance			
		MIN	TYP	MAX	Unit
RX sensitivity	BPSK rate 1/2, 6 Mbps OFDM	-	-93.4	-	dBm
	BPSK rate 3/4, 9 Mbps OFDM	-	-91.1	-	dBm
	QPSK rate 1/2, 12 Mbps OFDM	-	-90.3	-	dBm
	QPSK rate 3/4, 18 Mbps OFDM	-	-87.9	-	dBm
	16QAM rate 1/2, 24 Mbps OFDM	-	-84.6	-	dBm
	16QAM rate 3/4, 36 Mbps OFDM	-	-81.2	-	dBm
	64QAM rate 1/2, 48 Mbps OFDM	-	-77.0	-	dBm
	64QAM rate 3/4, 54 Mbps OFDM	-	-75.7	-	dBm
RX Sensitivity BW=20MHz Mixed mode 800ns Guard Interval Non-STBC	MCS 0, BPSK rate 1/2	-	-92.7	-	dBm
	MCS 1, QPSK rate 1/2	-	-89.5	-	dBm
	MCS 2, QPSK rate 3/4	-	-87.1	-	dBm
	MCS 3, 16QAM rate 1/2	-	-84.1	-	dBm
	MCS 4, 16QAM rate 3/4	-	-80.6	-	dBm
	MCS 5, 64QAM rate 2/3	-	-76.2	-	dBm
	MCS 6, 64QAM rate 3/4	-	-74.8	-	dBm
	MCS 7, 64QAM rate 5/6	-	-73.6	-	dBm
RX Sensitivity BW=40MHz Mixed mode 800ns Guard Interval Non-STBC	MCS 0, BPSK rate 1/2	-	-89.6	-	dBm
	MCS 1, QPSK rate 1/2	-	-86.8	-	dBm
	MCS 2, QPSK rate 3/4	-	-84.3	-	dBm
	MCS 3, 16QAM rate 1/2	-	-80.8	-	dBm
	MCS 4, 16QAM rate 3/4	-	-77.7	-	dBm
	MCS 5, 64QAM rate 2/3	-	-73.1	-	dBm
	MCS 6, 64QAM rate 3/4	-	-71.8	-	dBm
	MCS 7, 64QAM rate 5/6	-	-70.6	-	dBm
Maximum Receive Level	6 Mbps OFDM	-	-10	-	dBm
	54 Mbps OFDM	-	-10	-	dBm
	MCS0	-	-10	-	dBm
	MCS7	-	-20	-	dBm
Receive Adjacent Channel Rejection	1 Mbps CCK	-	40	-	dBm
	11 Mbps CCK	-	40	-	dBm
	BPSK rate 1/2, 6 Mbps OFDM	-	34	-	dBm

Parameter	Description	Performance			
		MIN	TYP	MAX	Unit
	64QAM rate 3/4, 54 Mbps OFDM	-	22	-	dBm
	HT20, MCS 0, BPSK rate 1/2	-	33	-	dBm
	HT20, MCS 7, 64QAM rate 5/6	-	15	-	dBm
	HT40, MCS 0, BPSK rate 1/2	-	29	-	dBm
	HT40, MCS 7, 64QAM rate 5/6	-	9	-	dBm

3.1.3 Wi-Fi 2.4GHz Band RF Transmitter Specifications

The specifications in table are measured at the antenna port, which includes the front-end loss.

Table 3-2. 2.4GHz RF Transmitter Specifications

Parameter	Description	Performance			
		MIN	TYP	MAX	Unit
Frequency range		2412	-	2484	MHz
Output power with spectral mask and EVM compliance	1 Mbps CCK	-	21	-	dBm
	11 Mbps CCK	-	21	-	dBm
	6 Mbps OFDM	-	19	-	dBm
	54 Mbps OFDM	-	18	-	dBm
	HT20, MCS 0	-	18	-	dBm
	HT20, MCS 7	-	17.5	-	dBm
	HT40, MCS 0	-	17	-	dBm
	HT40, MCS 7	-	16.5	-	dBm
TX EVM	6 Mbps OFDM	-	-	-5	dB
	54 Mbps OFDM	-	-	-25	dB
	HT20, MCS 0	-	-	-5	dB
	HT20, MCS 7	-	-	-28	dB
	HT40, MCS 0	-	-	-5	dB
	HT40, MCS 7	-	-	-28	dB
Output power variation ⁽¹⁾	TSSI closed-loop control across all temperature range and channels and VSWR \leq 1.5:1.	-1.5	-	1.5	dB
Carrier suppression		-	-	-30	dBc
Harmonic Output	2nd Harmonic	-	-45	-43	dBm/MHz

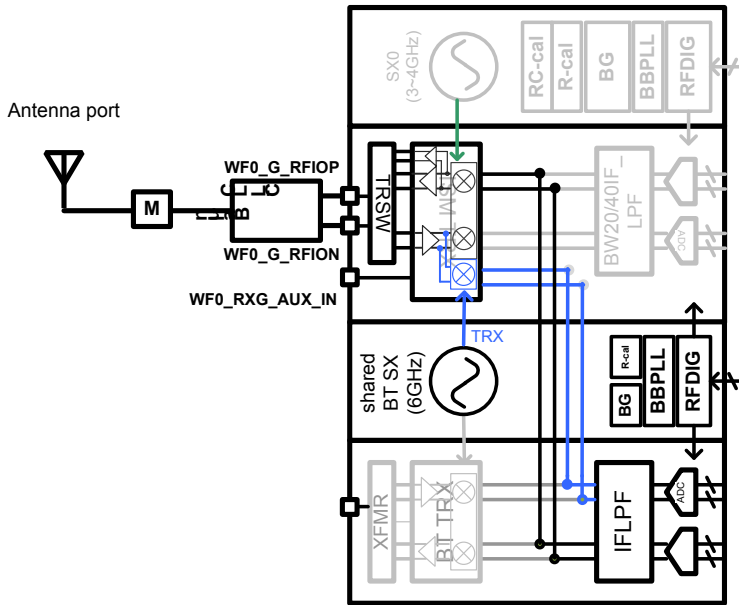
Parameter	Description	Performance			
		MIN	TYP	MAX	Unit
Power	3rd Harmonic	-	-45	-43	dBm/MHz

Note 1: VDD33 voltage is within ±5% of typical value.

3.2 Bluetooth Radio Characteristics

3.2.1 Bluetooth RF block diagram

Front-end loss with external Balun and diplexer: 2.4GHz insertion loss 2dB.



Note: **M** is matching circuits for 50ohm impedance tuning.

Figure 3-2. Wi-Fi/Bluetooth RF Block Diagram

3.2.2 Basic Rate Receiver Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

Figure 3-3. Basic Rate Receiver Specifications

PARAMETER	DESCRIPTION	PERFORMANCE
-----------	-------------	-------------

		MIN	TYP	MAX	UNIT
Frequency range		2402	-	2480	MHz
Receiver sensitivity ¹	BER<0.1%	-	-92	-	dBm
Maximum usable signal	BER<0.1%	-	-5	-	dBm
C/I co-channel (BER<0.1%)	Co channel selectivity	-	6	11	dB
C/I 1MHz (BER<0.1%)	Adjacent channel selectivity	-	-7	0	dB
C/I 2MHz (BER<0.1%)	2 nd adjacent channel selectivity	-	-40	-30	dB
C/I ≥3MHz (BER<0.1%)	3 rd adjacent channel selectivity	-	-43	-40	dB
C/I Image channel (BER<0.1%)	Image channel selectivity	-	-20	-9	dB
C/I Image 1MHz (BER<0.1%)	1MHz adjacent to image channel selectivity	-	-35	-20	dB
Inter-modulation		-39	-30	-	dBm
Out-of-band blocking	30MHz to 2000MHz	-10	-	-	dBm
	2000MHz to 2399MHz	-27	-	-	dBm
	2498MHz to 3000MHz	-27	-	-	dBm
	3000MHz to 12.75GHz	-10	-	-	dBm

Note 1: The receiver sensitivity is measured at the antenna port.

3.2.3 Basic Rate Transmitter Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

Table 3-3. Basic Rate Transmitter Specifications

PARAMETER	DESCRIPTION	PERFORMANCE			
		MIN	TYP	MAX	UNIT
Frequency range		2402	-	2480	MHz
Maximum transmit power ¹	At maximum power output level	-	10	-	dBm
Gain step		2	4	8	dB
Modulation characteristics	Δf_{1avg}	140	157	175	KHz
	Δf_{2max} (For at least 99.9% of all Δf_{2max})	115	121	-	KHz
	$\Delta f_{1avg} / \Delta f_{2avg}$	0.8	0.85	-	KHz

PARAMETER	DESCRIPTION	PERFORMANCE			
		MIN	TYP	MAX	UNIT
ICFT	Initial carrier frequency tolerance	-75	±20	+75	KHz
Carrier frequency drift	One slot packet (DH1)	-25	±15	+25	KHz
	Two slot packet (DH3)	-40	±15	+40	KHz
	Five slot packet (DH5)	-40	±15	+40	KHz
	Max drift rate	-20	±15	20	KHz/50µs
TX output spectrum	20dB bandwidth	-	-	1000	KHz
In-Band spurious emission	±2MHz offset	-	-40	-20	dBm
	±3MHz offset	-	-45	-40	dBm
	>±3MHz offset	-	-45	-40	dBm

Note 1: The output power is measured at the antenna port.

3.2.4 Enhanced Data Rate Receiver Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

Table 3-4. Enhanced Data Rate Receiver Specifications

PARAMETER	DESCRIPTION	PERFORMANCE			
		MIN	TYP	MAX	UNIT
FREQUENCY RANGE		2402	-	2480	MHZ
RECEIVER SENSITIVITY (BER<0.01%)	π/4 DQPSK	-	-91	-	DBM
	8PSK	-	-85	-	DBM
MAXIMUM USABLE SIGNAL (BER<0.1%)	π/4 DQPSK	-	-5	-	DBM
	8PSK	-	-5	-	DBM
C/I CO-CHANNEL (BER<0.1%)	π/4 DQPSK	-	9	13	DB
	8PSK	-	15	21	DB
C/I 1MHZ (BER<0.1%)	π/4 DQPSK	-	-5	0	DB
	8PSK	-	-5	5	DB
C/I 2MHZ (BER<0.1%)	π/4 DQPSK	-	9	-30	DB
	8PSK	-	15	-25	DB
C/I≥3MHZ (BER<0.1%)	π/4 DQPSK	-	-12	-40	DB
	8PSK	-	-6	-33	DB

C/I IMAGE CHANNEL (BER<0.1%)	$\pi/4$ DQPSK	-	-40	-7	DB
	8PSK	-	-36	0	DB
C/I IMAGE 1MHZ (BER<0.1%)	$\pi/4$ DQPSK	-	-43	-20	DB
	8PSK	-	-40	-13	DB

3.2.5 Enhanced Data Rate Transmitter Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

PARAMETER	DESCRIPTION		PERFORMANCE			
			MIN	TYP	MAX	UNIT
Frequency range			2402	-	2480	MHz
Maximum transmit power ¹	$\pi/4$ DQPSK		-	7	-	dBm
	8PSK		-	7	-	dBm
Relative transmit power	$\pi/4$ DQPSK		-4	-1.5	1	dB
	8PSK		-4	-1.5	1	dB
Frequency stability	maximum carrier frequency stability, ω_0	$\pi/4$ DQPSK	-10	± 4	10	KHz
		8PSK	-10	± 4	10	KHz
	maximum carrier frequency stability, ω_i	$\pi/4$ DQPSK	-75	± 20	75	KHz
		8PSK	-75	± 20	75	KHz
	maximum carrier frequency stability, $ \omega_0 + \omega_i $	$\pi/4$ DQPSK	-75	± 20	75	KHz
		8PSK	-75	± 20	75	KHz
Modulation accuracy	RMS DEVM	$\pi/4$ DQPSK	-20	± 9	30	%
		8PSK	-13	± 9	20	%
	99% DEVM	$\pi/4$ DQPSK	-30	± 15	-	%
		8PSK	-20	± 12	-	%
	Peak DEVM	$\pi/4$ DQPSK	-35	± 28	35	%
		8PSK	-25	± 21	25	%
In-Band	± 1 MHz offset	$\pi/4$ DQPSK	-	-30	-26	dB

PARAMETER	DESCRIPTION		PERFORMANCE			
			MIN	TYP	MAX	UNIT
spurious emission	±1MHz offset	8PSK	-	-30	-26	dB
	±2MHz offset	$\pi/4$ DQPSK	-	-27	-20	dBm
	±2MHz offset	8PSK	-	-27	-20	dBm
	±3MHz offset	$\pi/4$ DQPSK	-	-42.5	-40	dBm
	±3MHz offset	8PSK	-	-42.5	-40	dBm

Note 1: The output power is measured at the antenna port.

3.2.6 Bluetooth LE Receiver Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

Table 3-5. Bluetooth LE Receiver Specifications

Parameter	Description	Min.	Typ.	Max.	Unit
Frequency Range		2402	-	2480	MHz
Receiver Sensitivity (*)	PER < 30.8%	-	-95	-	dBm
Max. Usable Signal	PER < 30.8%	-10	-5	-	dBm
C/I Co-channel	Co-channel selectivity (PER < 30.8%)	-	6	21	dB
C/I 1MHz	Adjacent channel selectivity (PER < 30.8%)	-	-7	15	dB
C/I 2MHz	2nd adjacent channel selectivity (PER < 30.8%)	-	-30	-17	dB
C/I ≥ 3 MHz	3rd adjacent channel selectivity (PER < 30.8%)	-	-33	-27	dB
C/I Image channel	Image channel selectivity (PER < 30.8%)	-	-20	-9	dB
C/I Image 1MHz	1MHz adjacent to image channel selectivity (PER < 30.8%)	-	-30	-15	dB
Inter-modulation		-50	-35		dBm
Out-of-band Blocking	30MHz to 2000MHz	-30	-	-	dBm
	2001MHz to 2339MHz	-35	-	-	dBm
	2501MHz to 3000MHz	-35	-	-	dBm

	3001MHz to 12.75GHz	-30	-	-	dBm
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3.2.7 Bluetooth LE Transmitter Specifications

The specifications in table below are measured at the antenna port, which includes the front-end loss.

Table 3-6. Bluetooth LE Transmitter Specifications

Parameter	Description	Min.	Typ.	Max.	Unit
Frequency Range		2402	-	2480	MHz
Output Power (*)	At max power output level	-20	6	10	dBm
Carrier Frequency Offset and Drift	Frequency offset	-150	-	150	kHz
	Frequency drift	-50	-	50	kHz
	Max. drift rate	-20	-	20	Hz/us
Modulation Characteristic	$\Delta f_{1_{avg}}$	225	-	275	kHz
	$\Delta f_{2_{max}}$ (For at least 99% of all $\Delta f_{2_{max}}$)	185	-	-	kHz
	$\Delta f_{2_{avg}}/\Delta f_{1_{avg}}$	0.8	0.94	-	Hz/Hz
In-band	$\pm 2M$ offset	-	-	-20	dBm
Spurious Emission	$>\pm 3MHz$ offset	-	-	-30	dBm

Note 1: The output power is measured at the antenna port.

4 Electrical Characteristics

4.1 Absolute Maximum Rating

Table 4-1 Absolute Maximum Rating

Symbol	Parameters	Maximum rating	Unit
VDD33	3.3V Supply Voltage	-0.3 to 3.63	V
T _{STG}	Storage Temperature	-40 to +125	°C
VESD	ESD protection (HBM)	2000	V

4.2 Recommended Operating Range

Table 4-2. Recommended Operating Range

Symbol	Supply Voltage	Source	Min	Typ	Max	Unit
AVDD45	AVDD45_BUCK, AVDD45_MISC	To be connected to external 3.3V supply	2.97	3.3	3.63	V
RTC_3V3	RTC_3V3	To be connected to external supply	1.6V		3.63	V
AVDD33	AVDD33_WF0_G_PA, AVDD33_WF0_G_TX, AVDD33_BT	To be connected to external 3.3V supply	2.97	3.3	3.63	V
DVDDIO	DVDDIO_D, DVDDIO_L, DVDDIO_R	To be connected to PMU_DIO33_OUT	2.97	3.3	3.63	
AVDD25	AVDD25_AUXADC	To be connected to PMU ALDO output	2.3	2.5	2.7	V
AVDD16	AVDD16_CLDO, AVDD16_BT, AVDD16_XO, AVDD16_WF0_AFE	To be connected to PMU BUCK output	1.6	1.7	1.8	V
DVDD11	DVDD11	To be connected to PMU CLDO output	0.86	1.15	1.3	V
T _a	Operating Ambient Temperature	MT7697N	-30		85	C
		MT7697IN	-40		85	C
T _j	Operating Junction Temperature	MT7697N	-30		125	C
		MT7697IN	-40		125	C

4.3 DC Characteristics

Table 4-3. DC Characteristics

Symbol	Parameter	Conditions	MIN	MAX	Unit
V _{IL}	Input Low Voltage	LVTTTL	-0.28	0.8	V
V _{IH}	Input High Voltage		2	3.63	V

Symbol	Parameter	Conditions	MIN	MAX	Unit
V _{OL}	Output Low Voltage	I _{OL} = 4~16 mA	-0.28	0.4	V
V _{OH}	Output High Voltage	I _{OH} = 4~16 mA	2.4	VDD33+0.33	V
R _{PU}	Input Pull-Up Resistance	PU=high, PD=low	40	190	KΩ
R _{PD}	Input Pull-Down Resistance	PU=low, PD=high	40	190	KΩ

4.4 XTAL Oscillator

The table below lists the XTAL requirements for the XTAL.

Table 4-4. XTAL Oscillator Requirements

Parameter	Value
Frequency	26, 40, 52MHz.
Frequency stability	±10 ppm @ 25°C
Aging	±3 ppm/year

4.5 PMU Characteristics

Table 4-5. PMU Electrical Characteristics

Parameter	Reference	Conditions	Min	Typ	Max	Unit	
Switching regulator (BUCK)							
V _{in}	Input Voltage	AVDD45_BUCK	2.97	3.3	3.63	V	
V _{out}	Output Voltage	LXBK	Switching operation	1.6	1.7	1.8	V
			Deep Sleep mode, SLDO-H enabled		1.8		V
I _{out}	Output Current		Switching operation			800	mA
			Deep Sleep mode, SLDO-H enabled			10	mA
			Over-current shutdown	960	1600	4000	mA
I _q	Quiescent Current			150		uA	
DC/DC	Line Regulation				1	%	
	Load regulation				0.05	mV/mA	
	Efficiency		V _{in} = 3.3V, I _{load} = 400mA	80	85		%
Core LDO (CLDO)							
V _{in}	Input	AVDD16_CLDO	1.6	1.7	1.8	V	
V _{out}	Output Voltage	AVDD12_VCORE	Normal operation	0.86	1.15	1.3	V
			Deep Sleep mode, SLDO-L		0.85		V

Parameter	Reference	Conditions	Min	Typ	Max	Unit
		enabled				
I _{out}	Output Current	Normal operation			420	mA
		Deep Sleep mode, SLDO-L enabled			10	mA
I _q	Quiescent Current			40	50	uA
Analog LDO (ALDO)						
V _{in}	Input Voltage		2.97	3.3	3.63	V
V _{out}	Output Voltage	AVDD25_ALDO				
			Normal operation	2.3	2.5	2.7
				0		V
I _{out}	Output Current				50	mA
I _q	Quiescent Current			25	50	uA
PMU						
V _{in}	Input Voltage	AVDD45, AVDD33 and DVDDIO	2.97	3.3	3.63	V
I _q	Quiescent Current				50	uA
		In Deep Sleep State				

4.6 Auxiliary ADC Characteristics

This section specifies the electrical characteristics of the auxiliary ADC.

Table 4-6. Auxiliary ADC Specifications

Symbol	Parameter	Min	Typical	Max	Unit
N	Resolution	-	12	-	Bit
FS	Sampling Rate @ N-Bit ⁽¹⁾	-	2	-	MSPS
V _{PP}	Input Swing ⁽²⁾	-	-	1.8	V
V _{IN}	Input voltage ⁽³⁾	0	-	1.8	V
R _{IN}	Input Impedance:				
	Unselected channel	400M	-	-	Ohm
	Selected channel	-	10K	-	
DNL	Differential Nonlinearity without dithering and averaging	-	± 1	± 2	LSB
INL	Integral Nonlinearity without dithering and averaging	-	± 2	± 4	LSB
DNL _{dither+average}	Differential Nonlinearity with dithering and averaging	-	± 0.5	± 1	LSB
INL _{dither+average}	Integral Nonlinearity with dithering and averaging	-	-	± 2	LSB

Symbol	Parameter	Min	Typical	Max	Unit
OE	Offset Error	-	-	± 10	mV
FSE	Full Swing Error	-	-	± 50	mV
SNR	Signal to Noise Ratio ⁽²⁾	60	63	66	dB
	Current Consumption	-	-	400	μA
	Power-Down Current	-	-	1	μA

Note 1: Given that FS=2MHz

Note 2: At 1K Hz Input Frequency

Note 3: 1.77V when dithering is on.

4.7 Thermal Characteristics

Θ_{JC} assumes that all the heat is dissipated through the top of the package, while Ψ_{Jt} assumes that the heat is dissipated through the top, sides, and the bottom of the package. Thus it is suggested to use Ψ_{Jt} to estimate the junction temperature.

Table 4-7. Thermal Characteristics

Symbol	Description	Performance	
		Typical	Unit
T_J	Maximum Junction Temperature (Plastic Package)	125	°C
Θ_{JA}	Junction to ambient temperature thermal resistance ^[1]	19.21	°C/W
Θ_{JC}	Junction to case temperature thermal resistance	7.33	°C/W
Ψ_{Jt}	Junction to the package thermal resistance ^[2]	1.65	°C/W

Note 1: JEDEC 51-7 system FR4 PCB size: 76.2mm x 114.3mm

Note 2: 8mm x 8mm QFN-68 package

5 Package Specifications

5.1 Pin Layout

MT7697 uses 8mm x 8mm QFN package of 68-pin with 0.4mm pitch.

Table 5-1. Pin Map

		68	67	66	65	64	63	62	61	60	59	58	57	56	55	54	53	52		
		NC	AVDD33	NC	AVDD33_WF0_G_TX	WF0_G_RFIOP	WF0_G_RFION	AVDD33_WF0_G_PA	WF0_RXG_AUX_IN	AVDD16_BT	AVDD33_BT	BT_RFIP	GPIO33	GPIO34	GPIO35	GPIO36	GPIO37	GPIO38		
1	AVDD33	VSS																	SYSRST_B	51
2	AVDD16_WF0_AFE																		GPIO39	50
3	AVDD16_XO																		DVDD11	49
4	XO																		DVDDIO_L	48
5	GPIO0																		GPIO57	47
6	GPIO1																		GPIO58	46
7	GPIO2																		GPIO59	45
8	GPIO3																		GPIO60	44
9	GPIO4																		AVDD25_AUXADC	43
10	GPIO5																		AVSS25_AUXADC	42
11	GPIO6																		AVSS45_BUCK	41
12	GPIO7																		LXBK	40
13	DVDDIO_R																		AVDD45_BUCK	39
14	DVDD11																		AVDD15_V2P5NA	38
15	GPIO24																		AVDD16_CLDO	37
16	DVDDIO_D																		AVDD12_VCORE	36
17	DVDD11																		PMU_TEST	35
		18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34		
		GPIO25	GPIO26	RTC_3V3	RTC_32K_XO	RTC_32K_XI	PMU_EN_RTC	GPIO32	GPIO31	GPIO27	GPIO30	GPIO28	GPIO29	PMU_DIO33_OUT	AVDD25_ALDO_OUT	PMU_EN_WF	ISO_INT_PMU_EN	AVDD45_MISC		

5.2 Pin Description

The section describes the pin functionality of MT7697 chip.

Table 5-2. Pin Descriptions

QFN	Pin Name	Pin description	PU/PD	I/O	Supply domain
Reset and Clocks					
51	SYSRST_B	External system reset active low	PU	Input	DVDDIO
4	XO	Crystal input or external clock input	N/A	Input	AVDD16_XO
3	AVDD16_XO	RF 1.6V power supply	N/A	Power	
Programmable I/O					
5	GPIO0	Programmable input/output	PU/PD	In/out	DVDDIO
6	GPIO1	Programmable input/output	PU/PD	In/out	DVDDIO
7	GPIO2	Programmable input/output	PU/PD	In/out	DVDDIO
8	GPIO3	Programmable input/output	PU/PD	In/out	DVDDIO
9	GPIO4	Programmable input/output	PU/PD	In/out	DVDDIO
10	GPIO5	Programmable input/output	PU/PD	In/out	DVDDIO
11	GPIO6	Programmable input/output	PU/PD	In/out	DVDDIO
12	GPIO7	Programmable input/output	PU/PD	In/out	DVDDIO
15	GPIO24	Programmable input/output	PU/PD	In/out	DVDDIO
18	GPIO25	Programmable input/output	PU/PD	In/out	DVDDIO
19	GPIO26	Programmable input/output	PU/PD	In/out	DVDDIO
26	GPIO27	Programmable input/output	PU/PD	In/out	DVDDIO
28	GPIO28	Programmable input/output	PU/PD	In/out	DVDDIO
29	GPIO29	Programmable input/output	PU/PD	In/out	DVDDIO
27	GPIO30	Programmable input/output	PU/PD	In/out	DVDDIO
25	GPIO31	Programmable input/output	PU/PD	In/out	DVDDIO
24	GPIO32	Programmable input/output	PU/PD	In/out	DVDDIO
57	GPIO33	Programmable input/output	PU/PD	In/out	DVDDIO
56	GPIO34	Programmable input/output	PU/PD	In/out	DVDDIO
55	GPIO35	Programmable input/output	PU/PD	In/out	DVDDIO
54	GPIO36	Programmable input/output	PU/PD	In/out	DVDDIO

QFN	Pin Name	Pin description	PU/PD	I/O	Supply domain
53	GPIO37	Programmable input/output	PU/PD	In/out	DVDDIO
52	GPIO38	Programmable input/output	PU/PD	In/out	DVDDIO
50	GPIO39	Programmable input/output	PU/PD	In/out	DVDDIO
47	GPIO57	Programmable input/output	PU/PD	In/out	DVDDIO
46	GPIO58	Programmable input/output	PU/PD	In/out	DVDDIO
45	GPIO59	Programmable input/output	PU/PD	In/out	DVDDIO
44	GPIO60	Programmable input/output	PU/PD	In/out	DVDDIO
RTC					
20	VRTC	RTC domain power supply	N/A	Power	
21	RTC_32K_XO	32KHz crystal	N/A	Analog	VRTC
22	RTC_32K_XI	32KHz crystal	N/A	Analog	VRTC
23	PMU_EN_RTC	PMU enable	N/A	Output	VRTC
WiFi Radio Interface					
1,67	AVDD33	RF 3.3v power supply	N/A	Power	
62	AVDD33_WF0_G_PA	RF 3.3v power supply	N/A	Power	
65	AVDD33_WF0_G_TX	RF 3.3v power supply	N/A	Power	
2	AVDD16_WF0_AFE	RF 1.6v power supply	N/A	Power	
66,68	NC	No Connected	N/A	Input	
61	WF0_RXG_AUX_IN	RF g-band auxiliary RF LNA port	N/A	Input	AVDD33_WF0_G
64	WF0_G_RFIOP	RF g-band RF port	N/A	In/out	AVDD33_WF0_G
63	WF0_G_RFION	RF g-band RF port	N/A	In/out	AVDD33_WF0_G
Bluetooth Radio Interface					
59	AVDD33_BT	RF 3.3v power supply	N/A	Power	
60	AVDD16_BT	RF 1.6v power supply	N/A	Power	
58	BT_RFIO	RF Bluetooth port	N/A	In/out	AVDD33_BT
PMU/BUCK					
41	AVSS45_BUCK	BUCK ground	N/A	Ground	
40	LXBK	BUCK output	N/A	Output	
39	AVDD45_BUCK	BUCK power supply	N/A	Input	
38	AVDD15_V2P5NA	BUCK internal circuit output cap	N/A	Output	
37	AVDD16_CLDO	CLDO supply	N/A	Input	
36	AVDD12_VCORE	CLDO output	N/A	Output	

QFN	Pin Name	Pin description	PU/PD	I/O	Supply domain
34	AVDD45_MISC	PMU supply	N/A	Input	
31	AVDD25_ALDO_OUT	2.5V ALDO output with external cap.	N/A	Output	
30	PMU_DIO33_OUT	This pin output is to provide 3.3V for all DVDDIO. And in OFF mode, this pin is 0V.	N/A	Output	
35	PMU_TEST	PMU test pin	N/A	Output	
33	ISO_INT_PMU_EN	Input 0V for non-RTC platform. Input 3.3V for RTC platform.	N/A	Input	
32	PMU_EN_WF	External PMU enable	N/A	Input	
Power Supplies					
43	AVDD25_AUXADC	Auxiliary ADC 2.5v power supply	N/A	Power	
42	AVSS25_AUXADC	Auxiliary ADC ground	N/A	Ground	
13	DVDDIO_R	Digital 3.3V input	N/A	Power	
16	DVDDIO_D	Digital 3.3V input	N/A	Power	
48	DVDDIO_L	Digital 3.3V input	N/A	Power	
14, 17, 30, 49	DVDD11	Digital 1.15V input	N/A	Power	
E-PAD	VSS	Common Ground	N/A	Ground	

5.3 Pin Multiplexing

The pin multiplexing could be controlled via the configuration register A (in TOP_AON domain) and the configuration register B (in TOP_OFF/N9 domain). When configuration register A is set to 0, the configuration register B determines the pin function. When configuration register A is not set to 0, the configuration register A determines the pin function.

The default function of each pin is highlighted with blue background.

The driving strength of all pins is programmable: 4mA, 8mA, 12mA, and 16mA. The default setting for all pins are 4mA.

Table 5-3. Pin Multiplexing

Pin	Pin alias	APGIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel		Pinx_pinmux_off_sel	
								Address	Value		Value
5	GPIO0	AGPIO	MCU_JTCK	I	I	PD	N9 JTAG debug port	0x8102_3020[3:0]	0	0x8002_5100[3:0]	0

Pin	Pin alias	APGPIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel		Pinx_pinmux_off_sel	
			ANTSEL[0]	O			RF control		-	0x8102_3020[3:0]=0	1
			UART0_RTS_CM4	O			UART0 RTS (CM4)		7		3
			GPIO_TOPOFF[0]	I/O			General purpose input output		-		5
			GPIO_TOPAON[0]	O			General purpose input output		8		-
			PWM[0]	I/O			Pulse-width-modulated output		9		-
			EINT[0]	I			External interrupt		3		-
6	GPIO1	AGPIO	MCU_JTMS	I	I	PD	N9 JTAG debug port	0x8102_3020[7:4]	0	0x8002_5100[7:4] (0x8102_3020[7:4]=0)	0
			ANTSEL[1]	O			RF control		-		1
			UART0_CTS_CM4	I			UART0 CTS (CM4)		7		3
			GPIO_TOPOFF[1]	I/O			General purpose input output		-		5
			GPIO_TOPAON[1]	I/O			General purpose input output		8		-
			PWM[1]	O			Pulse-width-modulated output		9		-
EINT[1]	I			External interrupt	3	-					
7	GPIO2	AGPIO	MCU_JTDI	I	I	PD	N9 JTAG debug port	0x8102_3020[11:8]	0	0x8002_5100[11:8] (0x8102_3020[11:8]=0)	0
			ANTSEL[2]	O			RF control		-		1
			MCU_AICE_TMSC	I/O			N9 debug		-		2
			UART0_RX_CM4	I			UART0 RX (CM4)		7		3
			SWD_CLK	O			CM4 SWD debug port		4		4
			GPIO_TOPOFF[2]	I/O			General purpose input output		-		5
			GPIO_TOPAON[2]	I/O			General purpose input output		8		-
			PWM[23]	O			Pulse-width-modulated output		9		-
WIC[0]	I			External interrupt	3	-					
8	GPIO3	AGPIO	MCU_JTRST_B	I	I	PD	N9 JTAG debug port	0x8102_3020[15:12]	0	0x8002_5100[15:12] (0x8102_3020[15:12]=0)	0
			ANTSEL[3]	O			RF control		-		1
			[Reserved]	I			[Reserved]		-		2
			UART0_TX_CM4	O			UART0 TX (CM4)		7		3
			SWD_DIO	I/O			CM4 SWD debug port		4		4
			GPIO_TOPOFF[3]	I/O			General purpose input output		-		5
			GPIO_TOPAON[3]	I/O			General purpose input output		8		-
			PWM[24]	O			Pulse-width-modulated output		9		-
			EINT[2]	I			External interrupt		3		-
PULSE_CNT	I			Pulse counter	2	-					
9	GPIO4	GPIO	MCU_DBGIN	I	I	PD	N9 JTAG debug port	0x8102_3020[19:16]	0	0x8002_5100[19:16] (0x8102_3020[19:16]=0)	0
			ANTSEL[4]	O			RF control		-		1
			MCU_AICE_TCKC	I			N9 debug		-		-
			SPI_DATA0_EXT *	I/O			External flash interface		7		3
			GPIO_TOPOFF[4]	I/O			General purpose input output		-		5
			GPIO_TOPAON[4]	I/O			General purpose input output		8		-
			PWM[2]	O			Pulse-width-modulated output		9		-
EINT[3]	I			External interrupt	3	-					
10	GPIO5	GPIO	[Debug flag]	O	O(Low)		Debug monitor pin	0x8102_3020[23:20]	0	0x8002_5100[23:20] (0x8102_3020[23:20]=0)	0
			ANTSEL[5]	O			RF control		-		1
			SPI_DATA1_EXT *	O			External flash interface		7		3
			GPIO_TOPOFF[5]	I/O	I		General purpose input output		-		5
			GPIO_TOPAON[5]	I/O			General purpose input output		8		-
			PWM[3]	O			Pulse-width-modulated output		9		-
EINT[4]	I			External interrupt	3	-					
11	GPIO6	GPIO	MCU_DBGACKN	O	O		N9 JTAG debug port	0x8102_3020[27:24]	0	0x8002_5100[27:24] (0x8102_3020[27:24]=0)	0
			ANTSEL[6]	O			RF control		-		1
			SPI_CS_1_M_CM4	O			SPI master chip select 1		7		3
			GPIO_TOPOFF[6]	I/O			General purpose input output		-		5
			GPIO_TOPAON[6]	I/O			General purpose input output		8		-
PWM[4]	O			Pulse-width-modulated output	9	-					

Pin	Pin alias	APGIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel	Pinx_pinmux_off_sel		
			EINT[5]	I			External interrupt	3	-		
12	GPIO7	GPIO	MCU_JTDO	O	O(Lo w)		N9 JTAG debug port	0	0x8002_5100[31:28] (0x8102_3020[31:28]=0)	0	
			ANTSEL[7]	O			RF control	-		1	
			SPI_CS_0_M_CM4	O			SPI master chip select 0	6		2	
			SPI_CS_EXT *	O			External flash interface	7		3	
			GPIO_TOPOFF[7]	I/O			General purpose input output	-		5	
			GPIO_TOPAON[7]				General purpose input output	8		-	
			PWM[5]	O			Pulse-width-modulated output	9		-	
			EINT[6]	I			External interrupt	3		-	
15	GPIO24	GPIO	[Reserved]				[Reserved]	-	0x8002_510C[3:0] (0x8102_302C[2:0]=0)	0	
			UART_DSN_TXD_N9	O			UART_DSN TX (N9)	-		1	
			SPI_MOSI_M_CM4	O			SPI master MOSI	6		2	
			SPI_DATA2_EXT *	I/O			External flash interface	7		3	
			I2C1_CLK	I/O			I2C1 CLK	4		4	
			GPIO_TOPOFF[24]	I/O			General purpose input output	-		5	
			GPIO_TOPAON[24]	I/O			General purpose input output	8		-	
			PWM[25]	O			Pulse width modulation	9		-	
			[Reserved]	I	I	PU	[Reserved]	1		-	
			[Reserved]	O			[Reserved]	2		-	
18	GPIO25	GPIO	[Reserved]				[Reserved]	-	0x8002_510C[7:4] (0x8102_302C[7:4]=0)	0	
			SPI_MISO_M_CM4	I			SPI master MISO	-		2	
			SPI_DATA3_EXT *	I/O			External flash interface	7		3	
			I2C1_DATA	I/O			I2C1 DATA	4		4	
			GPIO_TOPOFF[25]	I/O			General purpose input output	-		5	
			GPIO_TOPAON[25]	I/O			General purpose input output	8		-	
			PWM[26]	O			Pulse width modulation	9		-	
			[Reserved]	I/O	O	PU	Default: Low.	1		-	
			FRAME_SYNC *	I			3DD synchronization	2		-	
WIC[1]	I			External interrupt	3	-					
19	GPIO26	GPIO	[Reserved]				[Reserved]	-	0x8002_510C[11:8] (0x8102_302C[11:8]=0)	0	
			SPI_SCK_M_CM4	O			SPI master SCK	6		2	
			SPI_CLK_EXT *	O			External flash interface	7		3	
			I2S_TX	O			I2S TX	4		4	
			GPIO_TOPOFF[26]	I/O			General purpose input output	-		5	
			GPIO_TOPAON[26]	I/O			General purpose input output	8		-	
			PWM[27]	O			Pulse width modulation	9		-	
			[Reserved]	I/O	O	PU	Default: Low.	1		-	
26	GPIO27	GPIO	SWD_DIO	I/O			CM4 SWD debug port	5	0x8002_510C[15:12] (0x8102_302C[15:12]=0)	1	
			I2C0_CLK	O			I2C0 CLK	4		3	
			GPIO_TOPOFF[27]	I/O			General purpose input output	-		5	
			GPIO_TOPAON[27]	I/O			General purpose input output	8		-	
			PWM[28]	O			Pulse width modulation	9		-	
			[Reserved]	I	I		[Reserved]	1		-	
			PULSE_CNT	I			Pulse counter input	2		-	
WIC[2]	I			External interrupt	3	-					
28	GPIO28	GPIO	SWD_CLK	I			CM4 SWD debug port	5	0x8002_510C[19:16] (0x8102_302C[19:16]=0)	1	
			SPI_INT_S_N9	O			SPI	-		2	
			I2C0_DATA	O			I2C0 DATA	4		3	
			GPIO_TOPOFF[28]	I/O			General purpose input output	0		5	
			GPIO_TOPAON[28]	I/O			General purpose input output	8		-	
			PWM[29]	O			Pulse width modulation	9		-	
[Reserved]	I/O	I		[Reserved]	1	-					
29	GPIO29	GPIO	I2S_MCLK_S	O			I2S MCLK slave	0x8102_302C[23:20]	-	0x8002_510C[23:20]	0

Pin	Pin alias	APGIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel	Pinx_pinmux_off_sel	
			SPI_MOSI_S_CM4	I			SPI slave MOSI (CM4)	6	(0x8102_302C[23:20]=0)	1
			SPI_MOSI_S_N9	I			SPI slave MOSI (N9)	-		2
			SPI_MOSI_M_CM4	O			SPI master MOSI	7		3
			[Reserved]	O			[Reserved]	4		4
			GPIO_TOPOFF[29]	I/O			General purpose input output	-		5
			GPIO_TOPAON[29]	I/O			General purpose input output	8		-
			PWM[30]	O			Pulse width modulation	9		-
			[Reserved]	I/O	I		[Reserved]	1		-
			HOST_ACK	O				2		-
			WIC[3]	I			External interrupt	3		-
			[Reserved]	O			[Reserved]	5		0
27	GPIO30	GPIO	SPI_MISO_S_CM4	O			SPI slave MISO (CM4)	6	0x8102_302C[27:24] (0x8102_302C[27:24]=0)	1
			SPI_MISO_S_N9	O			SPI slave MISO (N9)	0		2
			SPI_MISO_M_CM4	I			SPI master MISO	7		3
			I2S_FS	I			I2S slave FS	4		4
			GPIO_TOPOFF[30]	I/O			General purpose input output	0		5
			GPIO_TOPAON[30]	I/O			General purpose input output	8		-
			PWM[31]	O			Pulse width modulation	9		-
			[Reserved]	I/O	I		[Reserved]	1		-
			HOST_EINT_B	I				2		-
25	GPIO31	GPIO	I2S_TX	O			I2S TX	5	0x8102_302C[31:28] (0x8102_302C[31:28]=0)	0
			SPI_SCK_S_CM4	I			SPI slave SCK (CM4)	6		1
			SPI_SCK_S_N9	I			SPI slave SCK (N9)	-		2
			SPI_SCK_M	O			SPI master SCK	7		3
			I2S_RX	I			I2S slave RX	4		4
			GPIO_TOPOFF[31]	I/O			General purpose input output	-		5
			GPIO_TOPAON[31]	I/O			General purpose input output	8		-
			PWM[32]	O			Pulse width modulation	9		-
			[Reserved]	I/O	I		[Reserved]	1		-
24	GPIO32	GPIO	[Reserved]	O			[Reserved]	5	0x8102_3030[3:0] (0x8102_3030[3:0]=0)	0
			SPI_CS_0_S_CM4	I			SPI slave CS (CM4)	6		1
			SPI_CS_0_S_N9	I			SPI slave CS (N9)	-		2
			SPI_CS_0_M	O			SPI master CS	7		3
			I2S_BCLK	I			I2S BCLK slave	4		4
			GPIO_TOPOFF[32]	I/O			General purpose input output	-		5
			GPIO_TOPAON[32]	I/O			General purpose input output	8		-
			PWM[33]	O			Pulse width modulation	9		-
			[Reserved]	I/O	I		[Reserved]	1		-
57	GPIO33	AGPIO	WIFI_INT_B	I/O	O	PU	External interrupt	0	0x8102_3030 [7:4] (0x8102_3030 [7:4]=0)	0
			ALL_INT_B	I/O			External interrupt	-		1
			SWD_DIO	I/O			CM4 SWD debug port	6		2
			IR_TX	O			IrDA TX	7		3
			ANTSEL[5]	O			RF control	4		4
			GPIO_TOPOFF[33]	I/O			General purpose input output	-		5
			GPIO_TOPAON[33]	I/O			General purpose input output	8		-
			PWM[34]	O			Pulse width modulation	9		-
			PULSE_CNT	I			Pulse counter	1		-
			WF_LED_B	O			LED output	2		-
56	GPIO34	AGPIO	WIC[5]	I			External interrupt	3	0x8102_3030 [11:8] (0x8102_3030 [11:8]=0)	-
			BT_INT_B	I/O	O	PU	External interrupt	0		0
			ALL_INT_B	I/O			External interrupt	-		1
			SWD_CLK	I			CM4 SWD debug port	6		2
			IR_RX	I			IrDA RX	7		3

Pin	Pin alias	APGIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel	Pinx_pinmux_off_sel
			ANTSEL[6]	O			RF control	4	4
			GPIO_TOPOFF[34]	I/O			General purpose input output	-	5
			GPIO_TOPAON[34]	I/O			General purpose input output	8	-
			PWM[35]	O			Pulse width modulation	9	-
			FRAME_SYNC *	I			3DD synchronization	1	-
			BT_LED_B	I/O			LED output	2	-
			WIC[6]	I			External interrupt	3	-
55	GPIO35	GPIO	UART_DSN_TXD_N9	O	O	PD	UART DSN TX (N9)	0	0
			UART_DBG_CM4	O			UART DBG TX (CM4)	7	3
			GPIO_TOPOFF[35]	I/O			General purpose input output	-	5
			GPIO_TOPAON[35]	I/O			General purpose input output	8	-
			I2S_TX	O			I2S TX	5	-
			PWM[18]	O			Pulse-width-modulated output	9	-
54	GPIO36	GPIO	[Reserved]				[Reserved]	-	0
			S2A_SPL_IN	I			SPI input	-	1
			UART1_RX_CM4	I			UART1 RX (CM4)	7	3
			GPIO_TOPOFF[36]	I/O			General purpose input output	-	5
			GPIO_TOPAON[36]	I/O			General purpose input output	8	-
			PWM[19]	O			Pulse-width-modulated output	9	-
			UART_RXD_N9	I	I	PU	UART RX (N9)	1	-
WIC[7]	I			External interrupt	3	-			
53	GPIO37	GPIO	UART_TXD_N9	O	O	PD	UART TX (N9)	0	0
			UART1_TX_CM4	O			UART1 TX (CM4)	7	3
			GPIO_TOPOFF[37]	I/O			General purpose input output	-	5
			GPIO_TOPAON[37]	I/O			General purpose input output	8	-
			PWM[20]	O			Pulse-width-modulated output	9	-
			EINT[20]	I			External interrupt	3	-
52	GPIO38	GPIO	UART_RTS_N9	O	O	PD	UART RTS (N9)	0	0
			PTA_EINT_B	I			Packet traffic arbitration	-	1
			IDC_DATA_OUT	O			UART IDC TX (N9)	-	2
			UART1_RTS_CM4	O			UART1 RTS (CM4)	7	3
			GPIO_TOPOFF[38]	I/O			General purpose input output	-	5
			GPIO_TOPAON[38]	I/O			General purpose input output	8	-
			PWM[21]	O			Pulse-width-modulated output	9	-
			WF_LED_B	I/O			LED output	2	-
			EINT[21]	I			External interrupt	3	-
SWD_DIO	I/O			CM4 SWD debug port	6	-			
50	GPIO39	GPIO	UART_CTS_N9	I	I	PU	UART CTS (N9)	0	0
			PTA_EINT_B	I			Packet traffic arbitration	-	1
			IDC_DATA_IN	I			UART IDC RX (N9)	-	2
			UART1_CTS_CM4	O			UART1 CTS (CM4)	7	3
			[Reserved]				[Reserved]	-	4
			GPIO_TOPOFF[39]	I/O			General purpose input output	-	5
			GPIO_TOPAON[39]	I/O			General purpose input output	8	-
			PWM[22]	O			Pulse-width-modulated output	9	-
			PULSE_COUNT *	I			Pulse counter	1	-
			BT_LED_B	I/O			LED output	2	-
			EINT[22]	I			External interrupt	3	-
SWD_CLK	I			CM4 SWD debug port	6	-			
47	GPIO57	AGPIO	PCM_CLK	I/O			PCM interface for Bluetooth	-	0
			S2A_SPL_CK	I				-	1
			MCU_AICE_TCKC	I			N9 debug	-	2
			GPIO_TOPOFF[57]	I/O			General purpose input output	-	5

Pin	Pin alias	APGIO/ GPIO	Name	Dir	Default dir	Default PU/PD	Description	Pinx_pinmux_aon_sel	Pinx_pinmux_off_sel	
			GPIO_TOPAON[57]	I/O			General purpose input output		8	-
			PWM[36]	O			Pulse-width-modulated output		9	-
			[Reserved]	I	I	PU	[Reserved]		1	-
			WIC[8]	I			External interrupt		3	-
			ADC_IN0	I			Auxiliary ADC input	0x8102_300C[6]	1	-
46	GPIO58	AGPIO	PCM_SYNC	I/O			PCM interface for Bluetooth	0x8102_303C[11:8]=0 (0x8102_300C[7]=0)	-	0
			S2A_SPI_OUT	O					-	1
			MCU_AICE_TMISC	I/O			N9 debug		-	2
			GPIO_TOPOFF[58]	I/O			General purpose input output		-	5
			GPIO_TOPAON[58]	I/O			General purpose input output		8	-
			PWM[37]	O			Pulse-width-modulated output		9	-
			[Reserved]	I	I	PU	[Reserved]		1	-
			WIC[9]	I			External interrupt		3	-
ADC_IN1	I			Auxiliary ADC input	0x8102_300C[7]	1	-			
45	GPIO59	AGPIO	PCM_OUT	O			PCM interface for Bluetooth	0x8102_303C [15:12] (0x8102_300C[8]=0)	-	0
			UART_DSN_TXD_N9	O			UART DSN TX (N9)		-	1
			SWD_DIO	I/O	I		CM4 debug port		6	2
			GPIO_TOPOFF[59]	I/O			General purpose input output		-	5
			GPIO_TOPAON[59]	I/O			General purpose input output		8	-
			PWM[38]	O			Pulse-width-modulated output		9	-
			WF_LED_B	I/O			LED output		1	-
			WIC[10]	I			External interrupt		3	-
ADC_IN2	I			Auxiliary ADC input	0x8102_300C[8]	1	-			
44	GPIO60	AGPIO	PCM_IN	I			PCM interface for Bluetooth	0x8102_303C [19:16]=0 (0x8102_300C[9]=0)	-	0
			SWD_CLK	I	I		CM4 SWD debug port		6	2
			GPIO_TOPOFF[60]	I/O			General purpose input output		-	5
			GPIO_TOPAON[60]	I/O			General purpose input output		8	-
			PWM[39]	O			Pulse-width-modulated output		9	-
			BT_LED_B	I/O			LED output		1	-
			PULSE_CNT	I			Pulse counter input		2	-
WIC[11]	I			External interrupt	3	-				
ADC_IN3	I			Auxiliary ADC input	0x8102_300C[9]	1	-			

Note: * not used in MT7697

5.4 Bootstrap

The section describes the bootstrap function.

The chip modes are sensed from the device pin during power up. After chip reset, the pull configuration are stored in a register and determine the device operation mode.

Table 5-4. Bootstrap Option– Flash Access Mode

Flash Access Mode	PIN53 (GPIO37)	Description
Normal mode	Pull-down ⁽¹⁾	Firmware jumps to flash.
Recovery mode	Pull-up	Firmware does not jump to flash and wait for UART command.

		This mode is used for the firmware to jump to SYSRAM after downloading code from UART.
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Note 1: No external pull-down resistor is required because internal pull-down is active during power up.

Table 5-5. Bootstrap Option – XTAL Clock Mode

XTAL Clock Mode	PIN12 (GPIO7)	PIN52 (GPIO38)	Description
40MHz	Pull-down	Pull-up	Uses 40MHz XTAL.
26MHz	Pull-up	Pull-down ⁽¹⁾	Uses 26MHz XTAL.
52MHz	Pull-up	Pull-up	Uses 52MHz XTAL.

Note 1: No external pull-down resistor is required because internal pull-down is active during power up.

Table 5-6. Bootstrap Option – 32KHz Clock Mode

32KHz clock mode	PIN11 (GPIO6)	Description
Internal 32KHz clock	Pull-down	32KHz clock sources from 40/26/52MHz clock.
External 32KHz clock	Pull-up	32KHz clock sources from external pin.

Table 5-7. Bootstrap Option – Chip Mode

Chip mode	PIN55 (GPIO35)	PIN10 (GPIO5)	PIN11 (GPIO6)	PIN12 (GPIO7)	PIN52 (GPIO38)	Description
Normal mode	Pull-down ⁽¹⁾	Don't care	32KHz clock mode control	XTAL clock mode control		Chip operates in normal mode.
Test mode	Pull-up					Chip operates in test mode.

Note 1: No external pull-down resistor is required because internal pull-down is active during power up.

Note 2: When in test mode, the XTAL input clock is 26MHz only.

Pins 10, 11, 12, 52, 53, and 55 are used for bootstrap. The system design should follow the following guideline:

- Those pins shall not be used as input functions because the signals from another device might affect the values sensed.
- Those pins shall not be used as an open-drain function because the pull-up resistor would affect the values sensed.

5.5 Package information

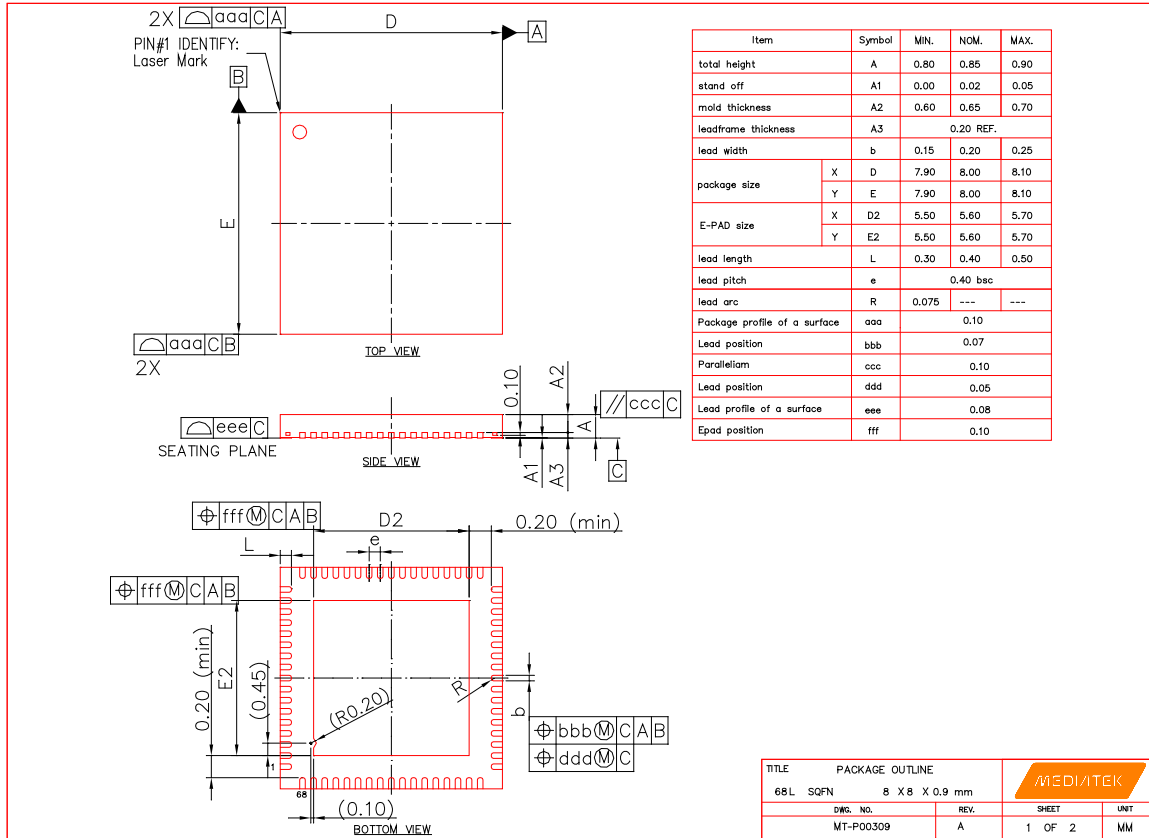


Figure 5-1. Package Outline Drawing

5.6 Ordering information

Table 5-8. Ordering Information

Part number	Package	Operational temperature range
MT7697N	8mm x 8mm x 0.8 mm QFN68	-30~85°C
MT7697IN	8mm x 8mm x 0.8 mm QFN68	-40~85°C

5.7 Top Marking

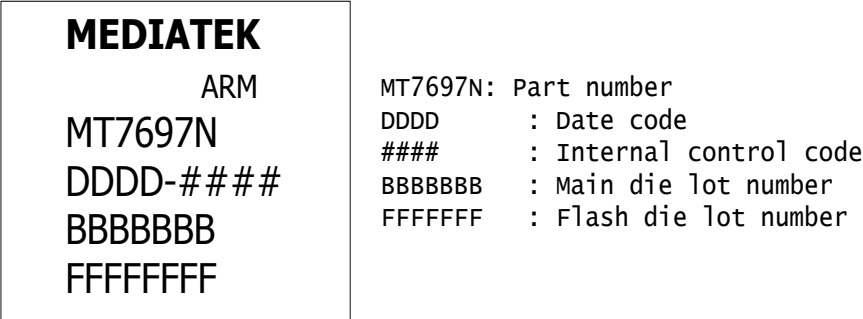


Figure 5-2. Top Marking